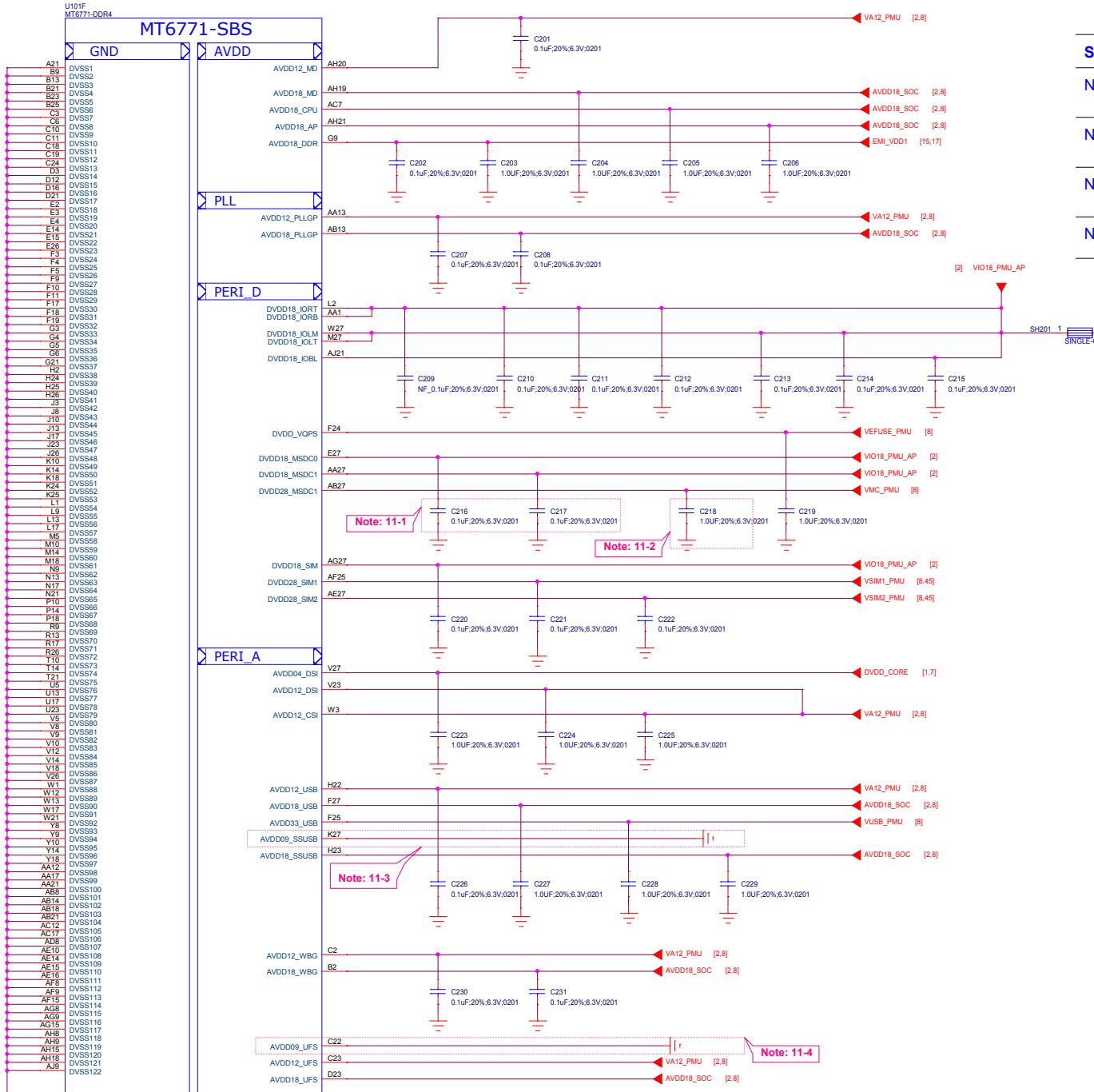


Schematic design notice of "10_BB_POWER_PDN" page.

- Note 10-1:** Differential pair of DVDD_GPU remote sense must be close to BB's ball.
Remote sense trace with GND shielding to PMIC (Differential)
- Note 10-2:** Differential pair of DVDD_PROC remote sense must be close to BB's ball.
Remote sense trace with GND shielding to PMIC (Differential)
- Note 10-3:** Differential pair of DVDD_MODEM remote sense must be close to BB's ball.
Remote sense trace with GND shielding to PMIC (Differential)
- Note 10-4:** Differential pair of DVDD_CORE remote sense must be close to BB's ball.
Remote sense trace with GND shielding to PMIC (Differential)

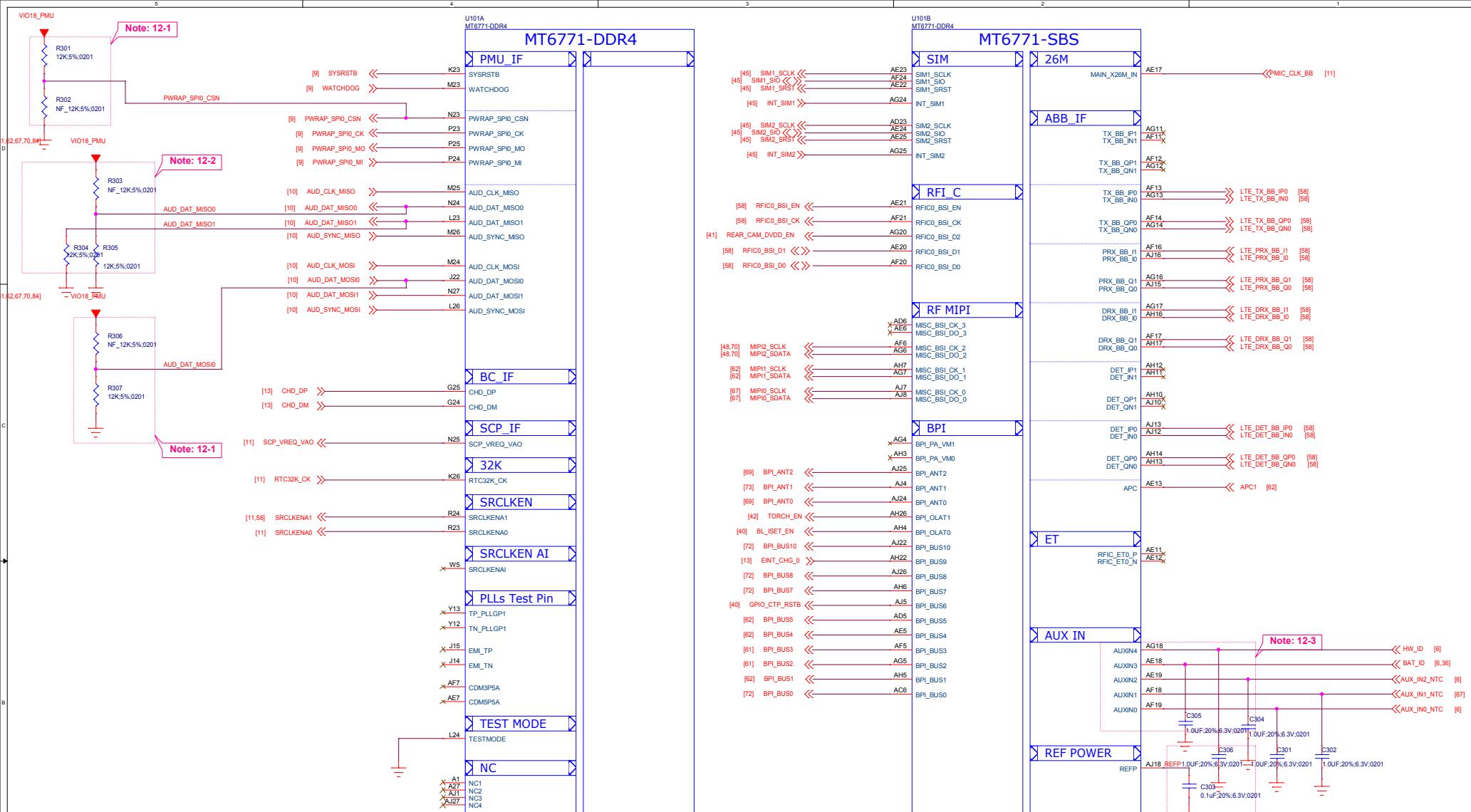
Title	01_BB_POWER_PDN	REV: V10
DOCUMENT NO.:	Design Name	Size: C
DEPARTMENT:	WINGTECH-SH	DESIGNER: LIUFENGLI
WINGTECH		
Date: Thursday, May 30, 2019	Sheet 3	of 65



Schematic design notice of "11_BB_POWER_IO" page.

- Note 11-1: C216 closed DVDD18_MSDC0 150mil
- Note 11-2: C217 closed DVDD18_MSDC1 150mil
- Note 11-3: Connects "AVDD09_SSUSB" to GND when USB3.0 is not used.
- Note 11-4: Connects "AVDD09_UFS" to GND when UFS is not used.

Title	02_BB_POWER_IO	REV: V10
DOCUMENT NO.:	Design Name	Size: C
DEPARTMENT:	WINGTECH-SH	DESIGNER: LIUFENGLI
WINGTECH		
Date: Thursday, May 30, 2019	Sheet 4	of 65



Schematic design notice of "12_BB_1" page.

Note 12-1: "PWRAP_SPI0_CSN" and "AUD_DAT_MOSI0" are bootstrap pins to select which interface will be the JTAG pin out.

PWRAP_SPI0_CSN	AUD_DAT_MOSI0	AP_JTAG	IO_JTAG
HI	LO	N/A	N/A
HI	HI	SPI_CSB/SPI_CLK/ SPI_MO/SPI_MIE/INT8	N/A
LO	LO	SPI_CSB/SPI_CLK/ SPI_MO/SPI_MIE/INT8	DPI_11/DPI_HSYNC/DPI_VSYNC/DPI_DE/ DPI_O/DPI_D8/DPI_D9
LO	HI	MSDC1_CLK/CMD/ DATA0/DAT1/DAT2	N/A

Note 12-2: "AUD_DAT_MISO0" is bootstrap pin to enable serial JTAG output over USB2.0 interface or not. When "AUD_DAT_MISO0" is pulled to high in system start up and then USB2.0 interface will be switched into serial JTAG mode.

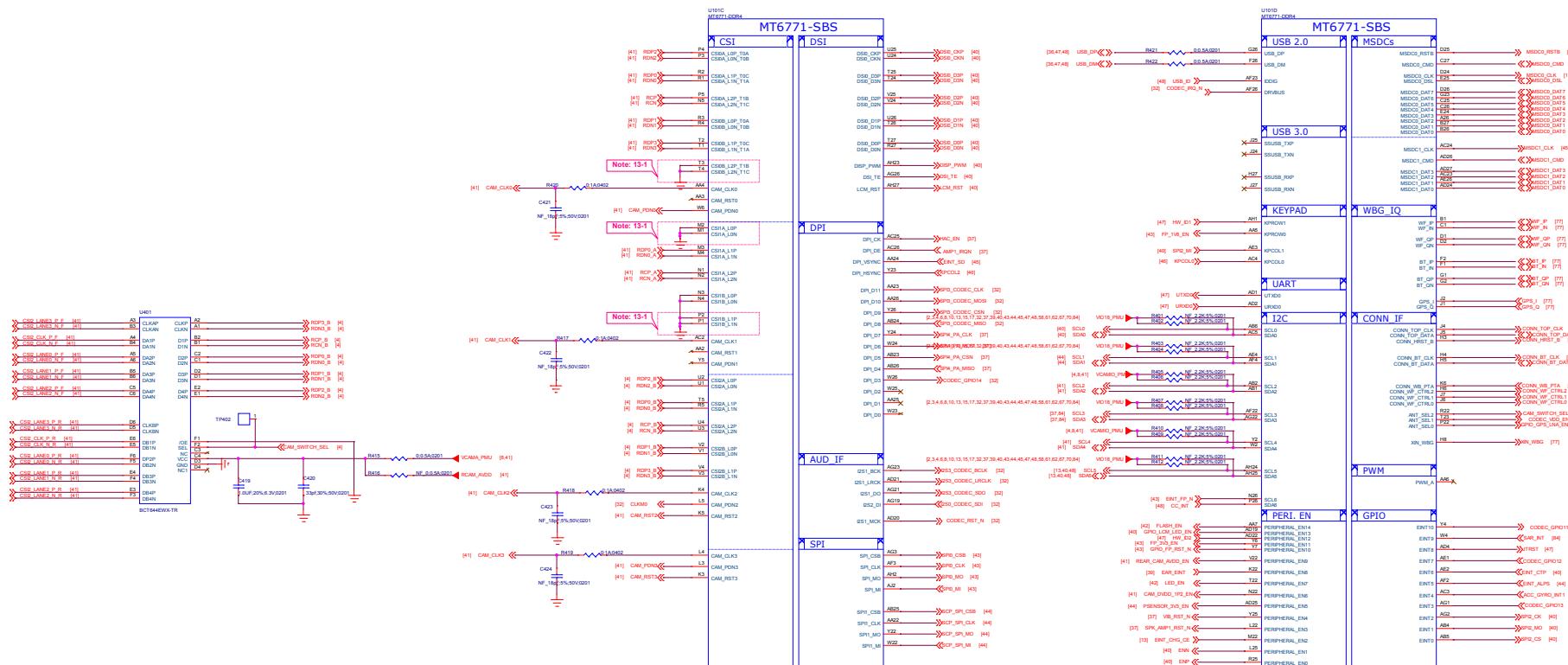
AUD_DAT_MISO1	Bootstrapping device
LO	eMMC
HI	UFS

Note 12-3: To shunt a 1uF capacitor in the AUXIN ADC input to prevent noise coupling. It should be placed as close to BB as possible. Connect the unused AUX ADC input to GND.

Note 12-4: The de-coupling cap. for REFP (AJ18 ball) have to be placed as close to BB as possible.

Note 12-5: AUD_SYNC_MISO and AUD_CLK_MISO are DDR type feature in bootstrap

AUD_SYNC_MISO	AUD_CLK_MISO	DDR
LO	LO	LPDDR4X
LO	HI	LPDDR4X(Ext x 2 EN)
HI	LO	LPDDR3
HI	HI	LPDDR4X(Ext x 1 EN)

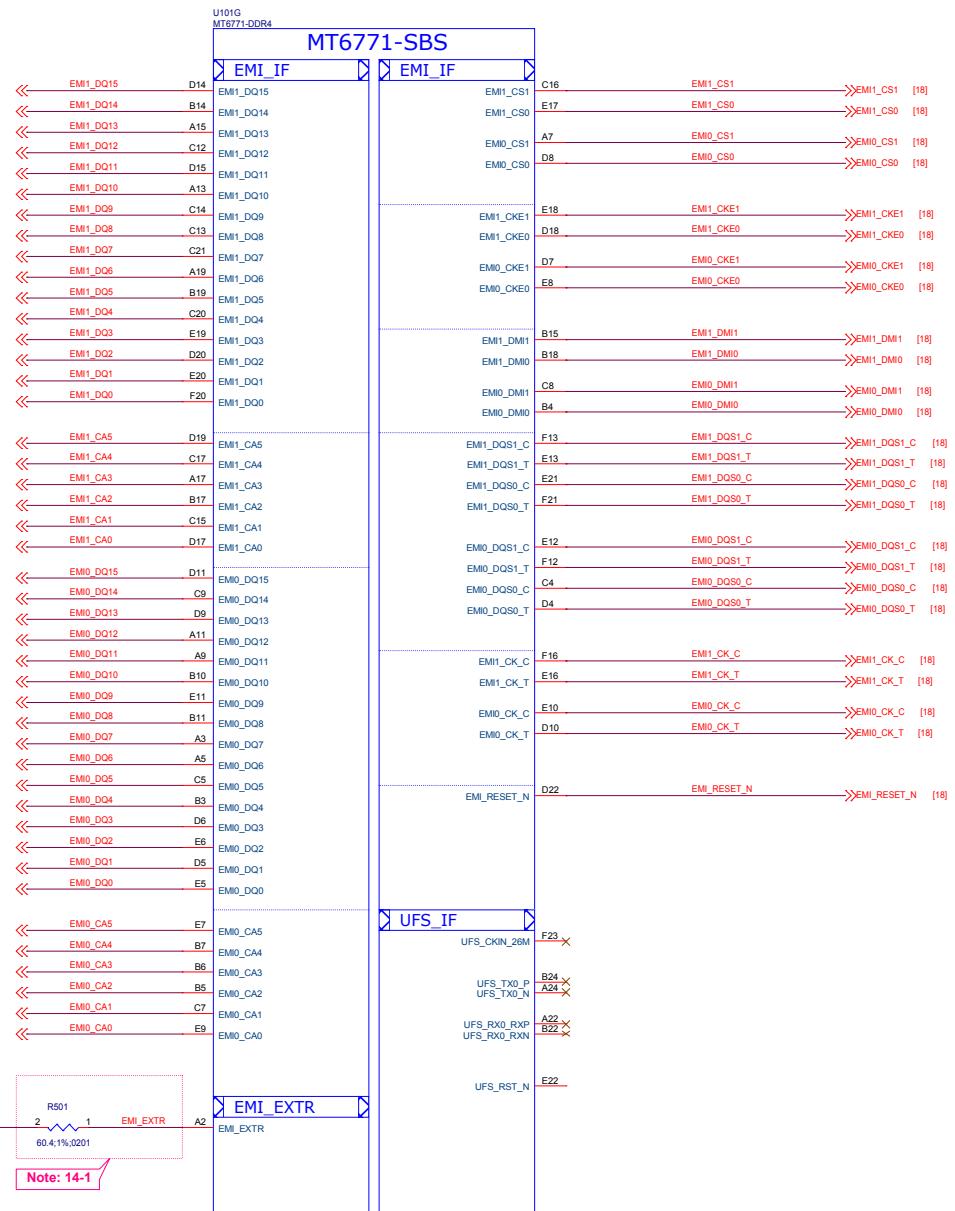


Schematic design notice of "13_BB_2" page.

Note 13-1: CSI ports which are no use could be connected to GND or set in NC.
For detail information, please refer to MT6771 Design Notice.

Page	04_BB_2_MIP&GPIO	Rev.	V10
DOCUMENT NO.	Design Name	Spec	D
DEPARTMENT:	WINGTECH-SH	DESIGNER:	LUFENG
Ver.:	Thursday, May 20, 2010	Sheet	6 of 60

WINGTECH

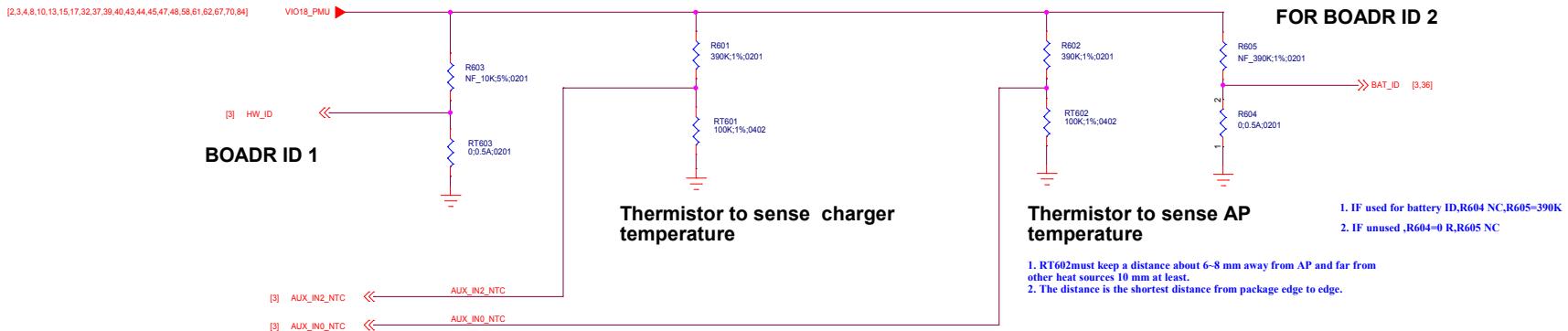


Schematic design notice of "14_BB_3" page.

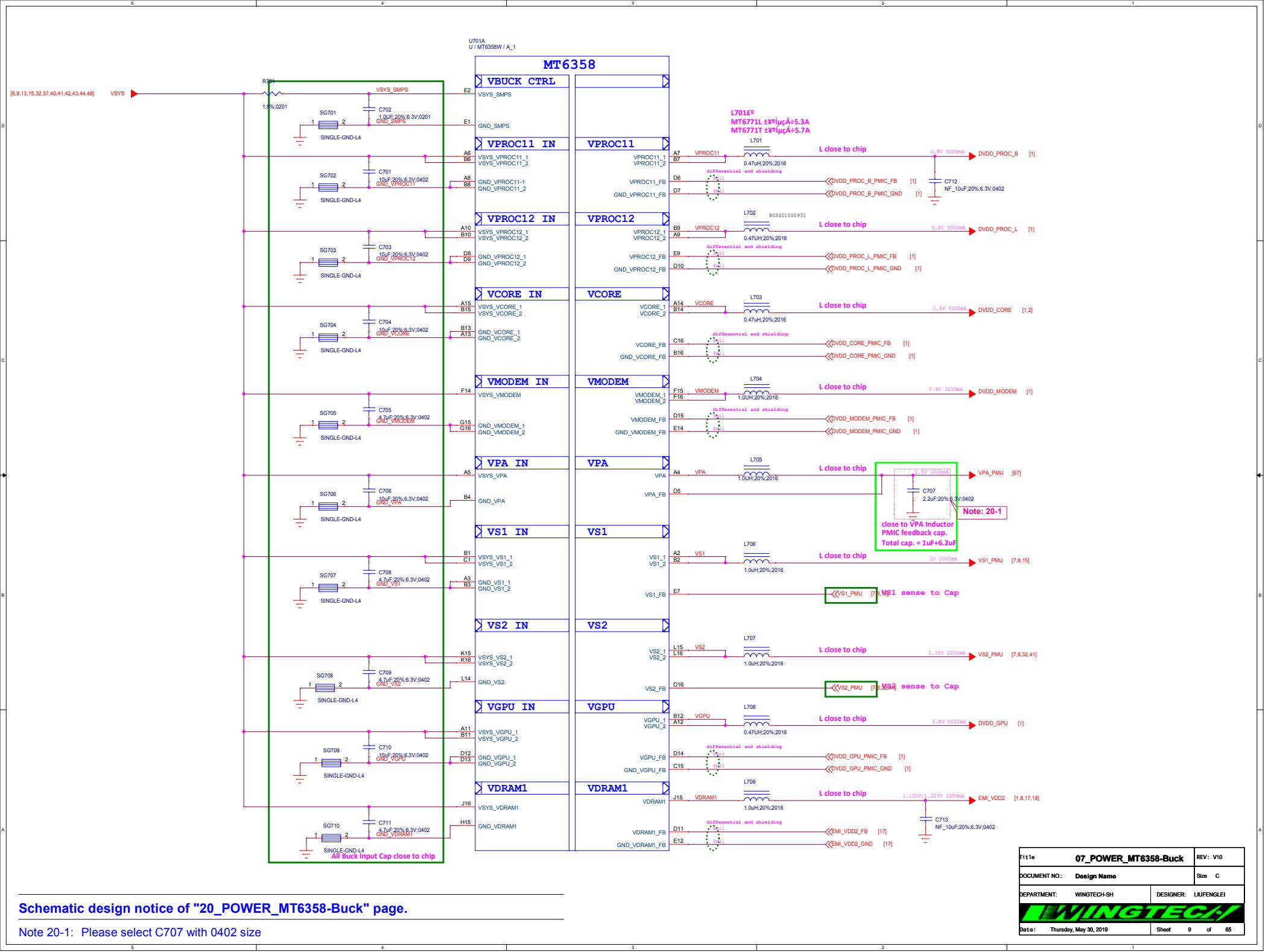
Note 14-1: The resistor of EMI_EXTR for DRAM has to be placed near to BB as close as possible
Note 14-1: R501, please select 60.4 ohm 1% resistor

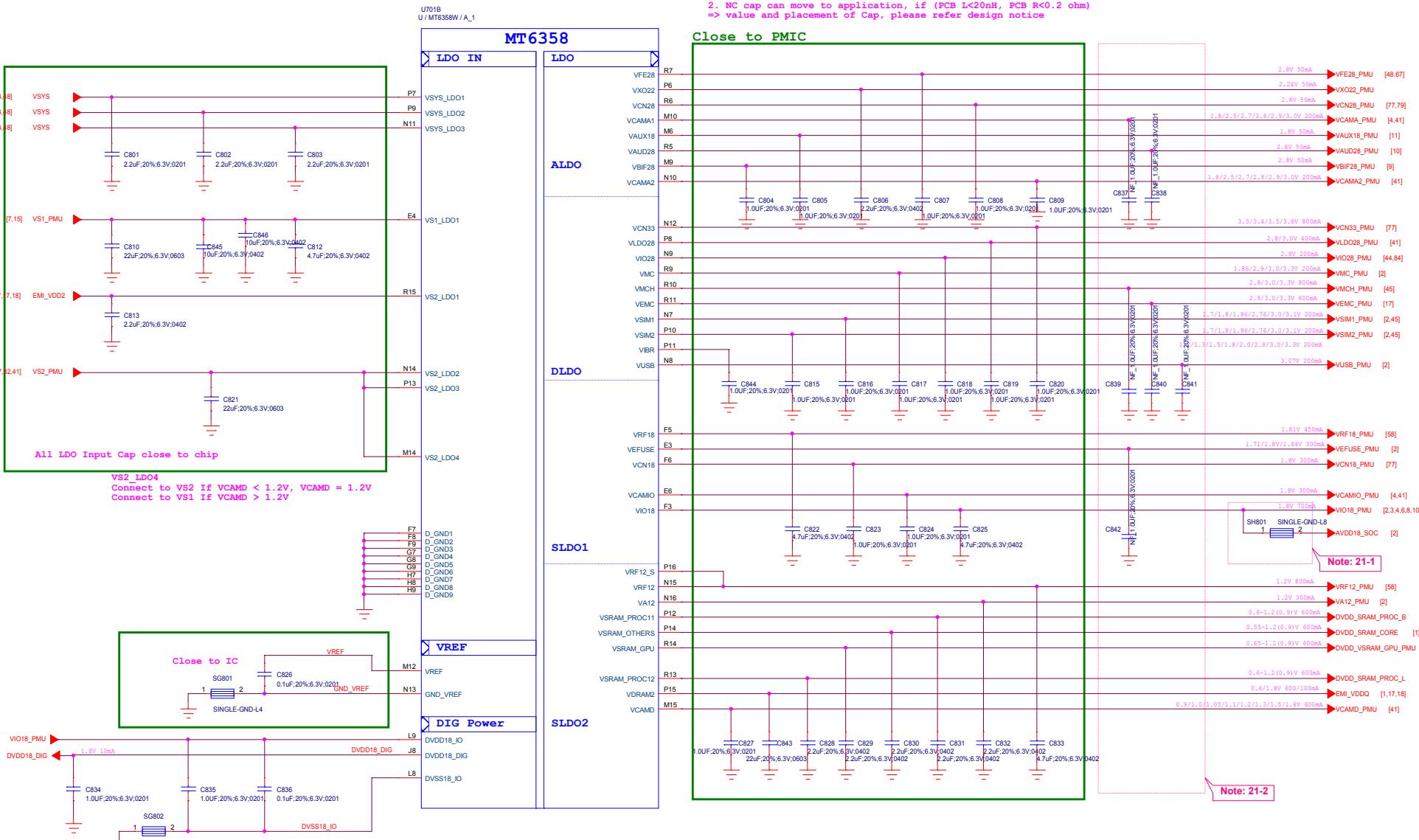
Title	10_BB_POWER_PDN	REV: V10
DOCUMENT NO:	Design Name	Size: C
DEPARTMENT:	WINGTECH-SH	DESIGNER: LIUFENGLEI
Date:	Thursday, May 30, 2019	Sheet 7 of 65

WINGTECH



Title 06_BB_AUXADC_Thermal		REV: V10
DOCUMENT NO.: Design Name		Size C
DEPARTMENT: WINGTECH-SH		DESIGNER: LIUENGLEI
Date: Thursday, May 30, 2019	Sheet 8	of 65





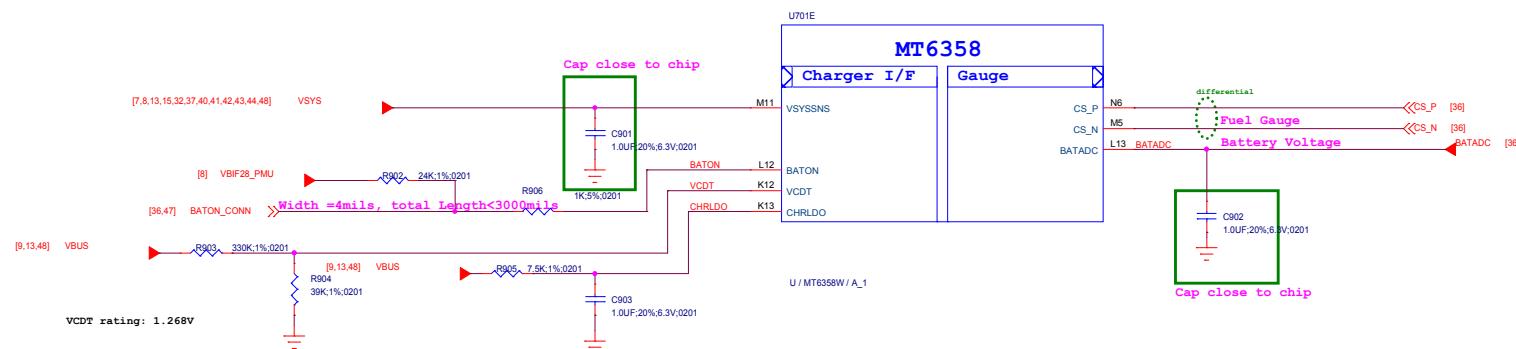
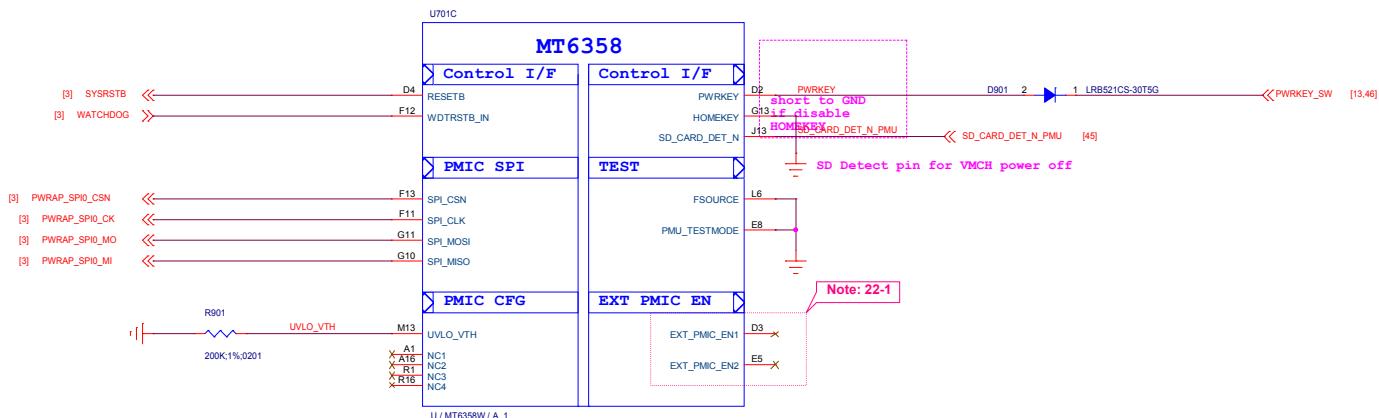
Schematic design notice of "21_POWER_MT6358-LDO" page.

Note 21-1: Please set SH801 close to C825, making star connection between VIO18_PMU and AVDD18_SOC near to LDO cap. C825

Please also refer to MT6358 design notice for further detail design information

Note 21-2: If these power trace can meet LDO layout constraint, these CAP can be NC or removed.
Please refer to MT6358 design notice.

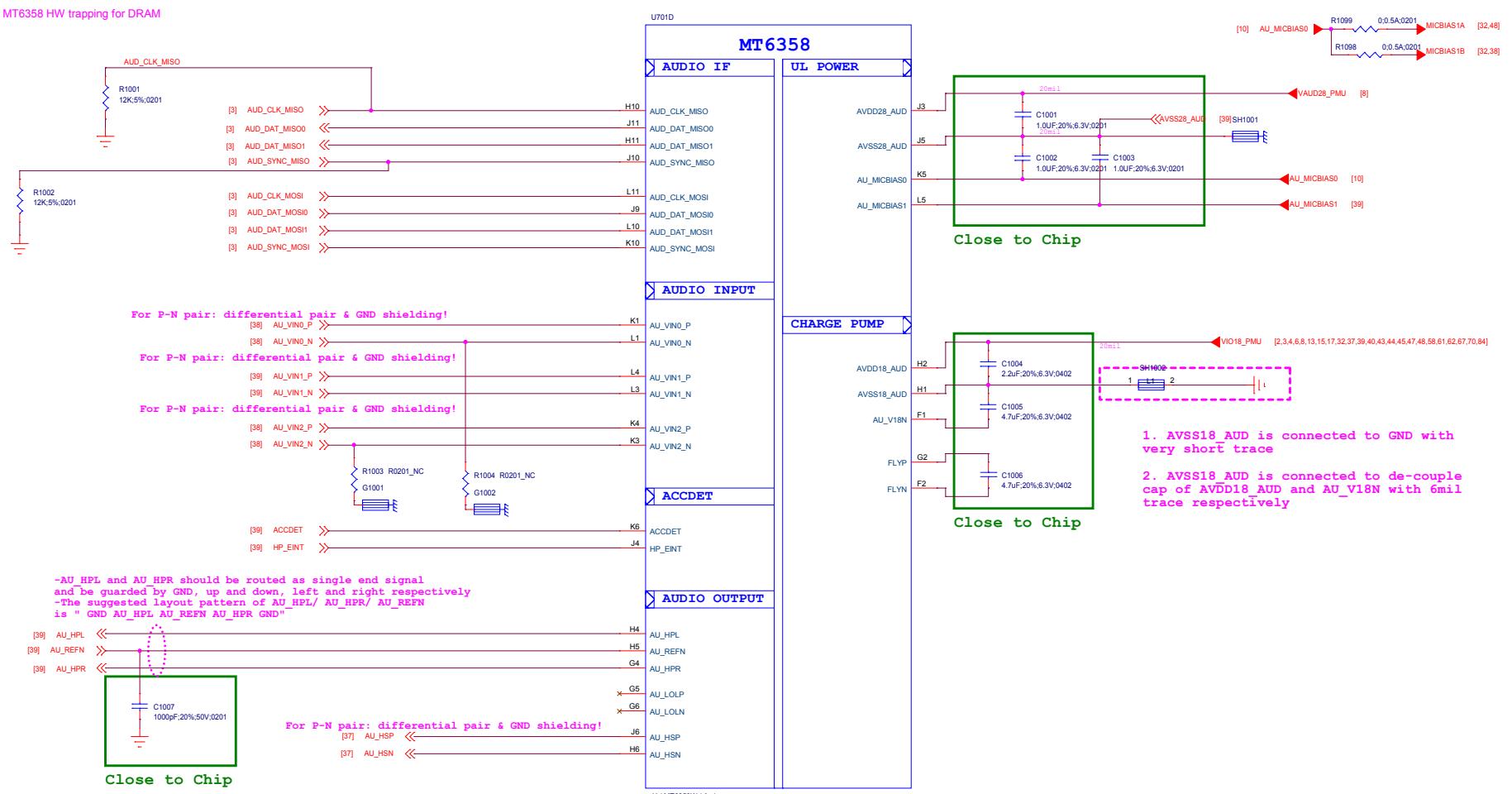
Title	08_POWER_MT6358-LDO	REV:	V10
DOCUMENT NO.:	Design Name	Size	C
DEPARTMENT:	WINGTECH-SH	DESIGNER:	LIUFENGLEI
WINGTECH		Date:	Thursday, May 30, 2019
		Sheet	10 of 65



Schematic design notice of "22 POWER MT6358-General"

Note 22-1: EXT_PMIC_EN1 : For UFS_1V8, and keep floating if it is not used
EXT_PMIC_EN2 : For VA09 of SSUSB/UFS, and keep floating if it is not used

Title	09_POWER_MT6358-General	REV: V10
DOCUMENT NO.:	Design Name	Size C
DEPARTMENT:	WINGTECH-SH	DESIGNER: LIUFENGLEI
WINGTECH		
Date:	Thursday, May 30, 2019	Sheet 11 of 65

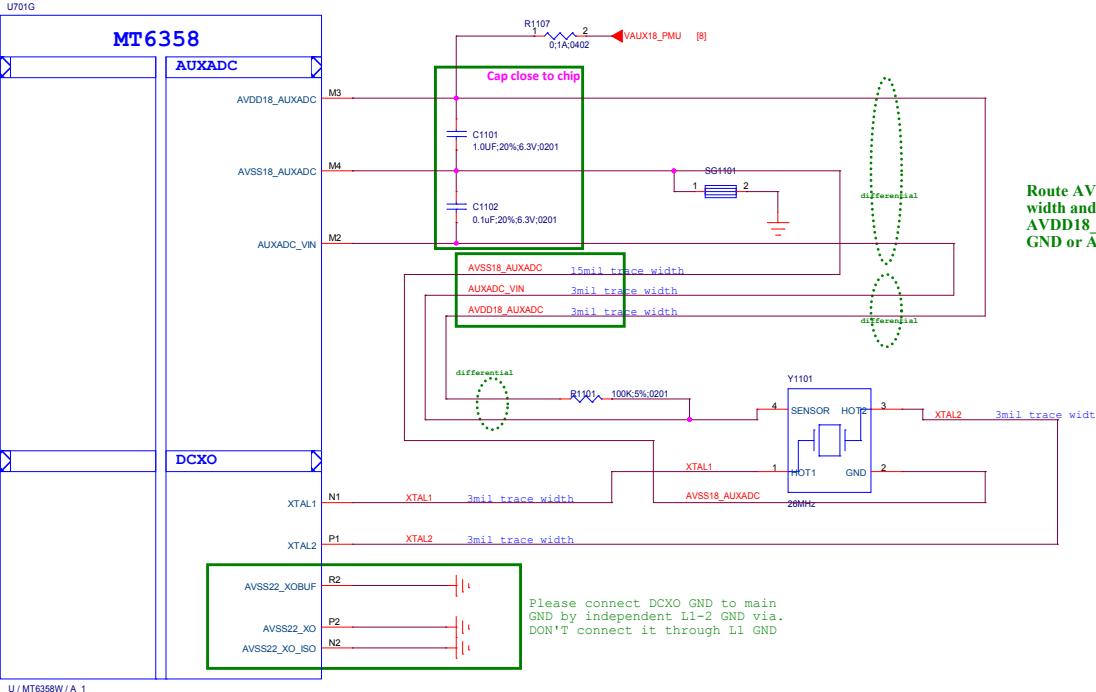


Schematic design notice of "23_POWER_MT6358-Audio"

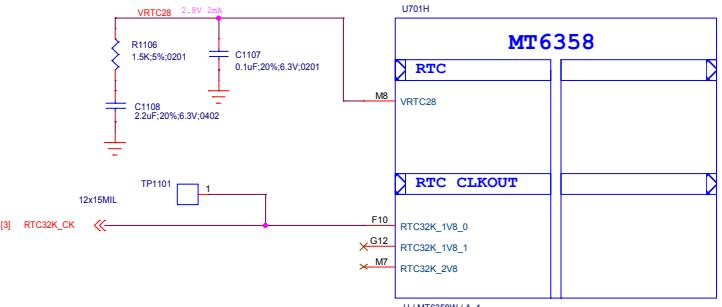
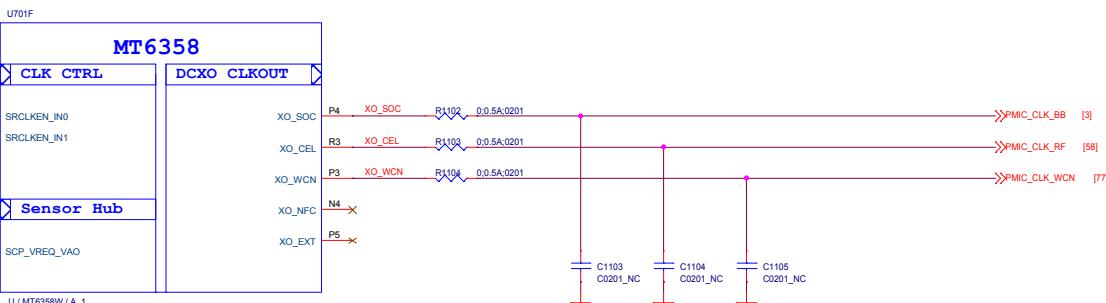
Note 23-1: VDRAM 2 / VDRAM1 output voltage vs. trap pin.

HW GPIO configuration		Trapping Option		DRAM type	VDRAM2 Power source (VS2_LDO1_ball)
AUD_SYNC_MISO	AUD_CLK_MISO	VDRAM1	VDRAM2		
0	0	1.125V	0.6V	LP4X	VDRAM1
0	1	OFF	1.8V	LP4X (Ext x 2 EN)	VS1
1	0	1.225V	OFF	LP3	VDRAM1
1	1	1.125V	1.8V	LP4X (Ext x 1 EN)	VS1

Title	10_POWER_MT6358-Audio		REV: V10
DOCUMENT NO.:	Design Name		Size C
DEPARTMENT:	WINGTECH-SH	DESIGNER:	LJUFENGLEI
			
Date:	Thursday, May 30, 2019		Sheet 12 of 65



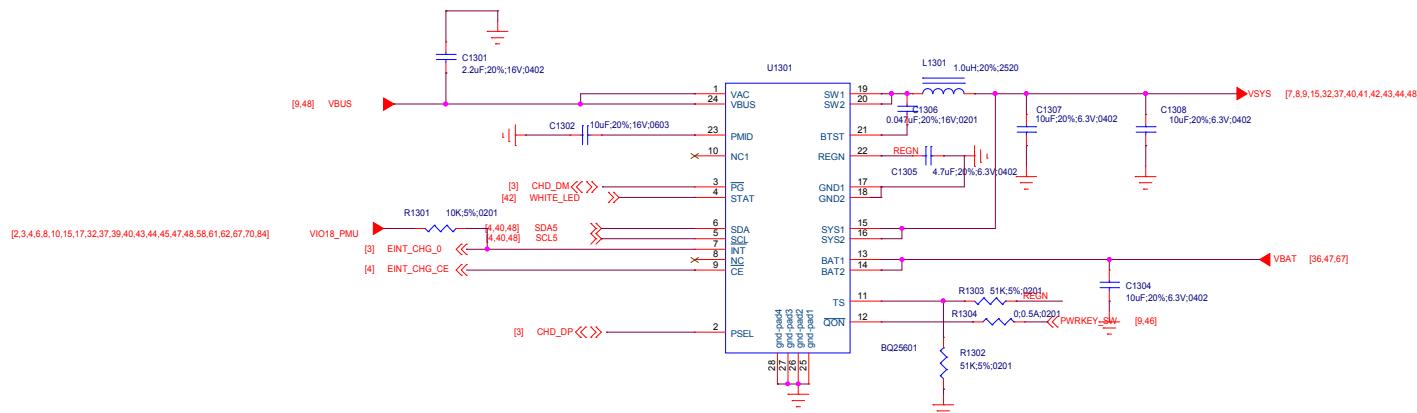
Route AVDD18_AUXADC/AUXADC_VIN with 3mil trace width and well GND shielding.
AVDD18_AUXADC/AUXADC_VIN need to be shielded with GND or AVSS18_AUXADC.



Title	11_POWER_MT6358_Clock	REV: V10
DOCUMENT NO.:	Design Name	Size: C
DEPARTMENT:	WINGTECH-SH	DESIGNER: LIUFENGLEI
Date:	Thursday, May 30, 2019	Sheet 13 of 65

D
D
C
C
B
B
A
A

Title	12_POWER_MT6370-General	REV: V10
DOCUMENT NO.:	Design Name	Size C
DEPARTMENT:	WINGTECH-SH	DESIGNER: LIUFENGLI
		Date: Thursday, May 30, 2019 Sheet 14 of 65



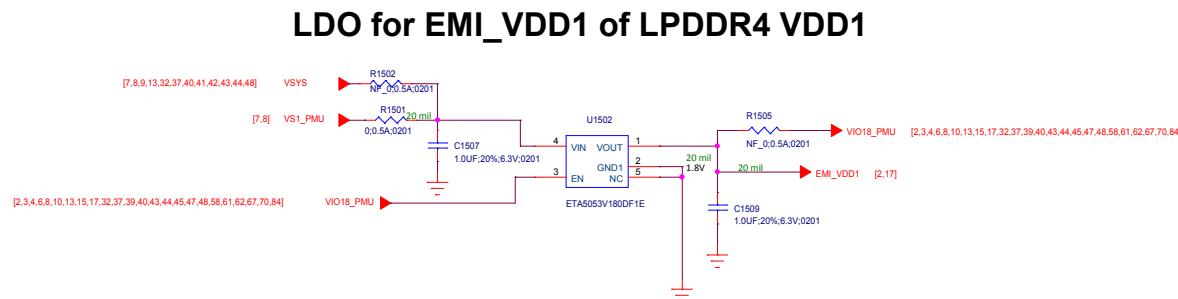
Title 13_POWER_MT6370-Charger + PP		REV: V10
DOCUMENT NO.:	Design Name	Size C
DEPARTMENT:	WINGTECH-SH	DESIGNER: LIUFENGLI
	Thursday, May 30, 2019	Sheet 15 of 65

Schematic design notice of "27_POWER_SubPMIC-HV powers" page.

Note 27-1: It is recommended to reserve 0-ohm and cap. for BOM fine tune to minimize RF de-sense.

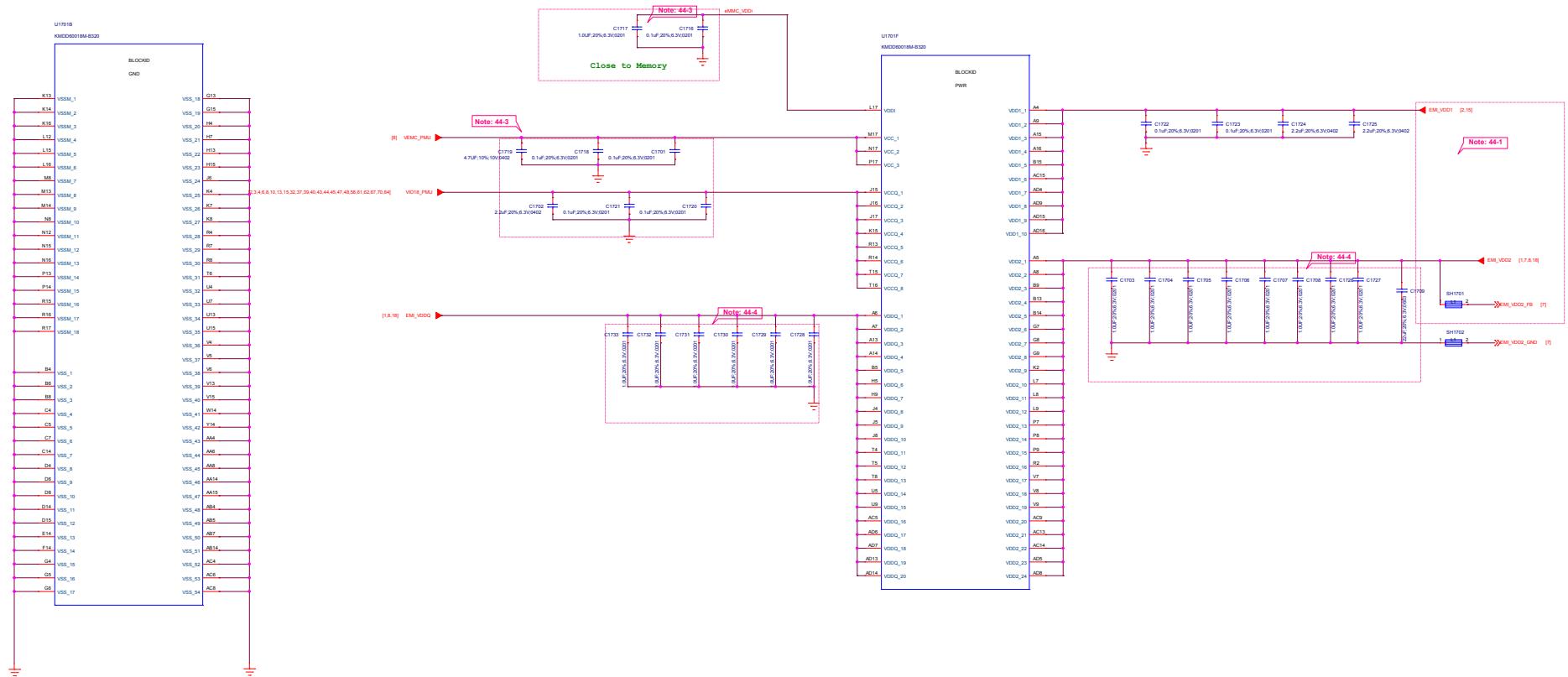
Note 27-2: It is recommended to reserve 0-ohm for BOM fine tune to minimize RF de-sense.

Title	14_POWER_MT6370-HV powers	REV: V10
DOCUMENT NO.:	Design Name	Size C
DEPARTMENT:	WINGTECH-SH	DESIGNER: LIUFENGLI
		Date: Thursday, May 30, 2019
	Sheet 16	of 65



Title 15_POWER_ThirdParty_Powers		REV: V10
DOCUMENT NO.: Design Name		Size C
DEPARTMENT: WINGTECH-SH		DESIGNER: LIUFENGLI
WINGTECH		Date: Thursday, May 30, 2019 Sheet 17 of 65

5	4	3	2	1
D				D
C				C
B				B
A				A
Title 16_BB_POWER_PDN REV: V10				
DOCUMENT NO.: Design Name		Size C		
DEPARTMENT: WINGTECH-SH		DESIGNER: LIUFENGLI		
				
Date: Thursday, May 30, 2019		Sheet 18 of 65		
5	4	3	2	1



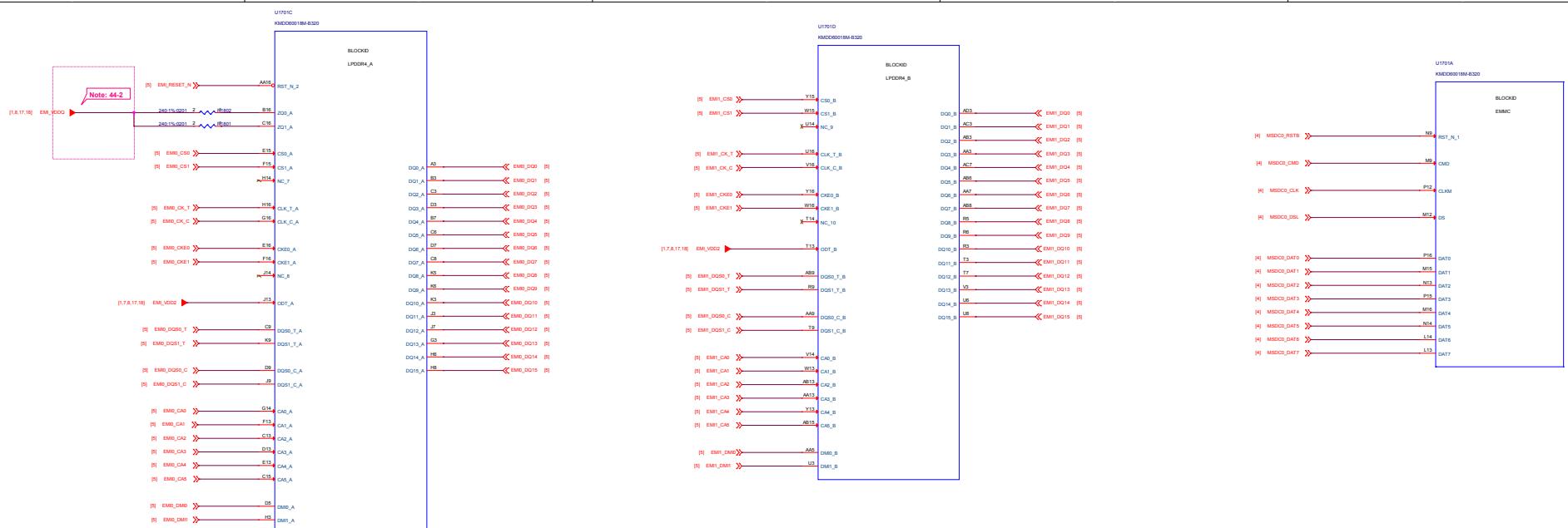
Schematic design notice of "44_Memory_eMMC_LPDDR4X"

Note 44-1: Please refer to power supply related page select VDRAM 2 / VDRAM1 output voltage properly for LPDDR4X

Note 44-2: DRAM ZQx resistor = 240ohm (1%) that must be connected to VDDQ,

Note 44-3: Please refer to eMCP vendor's datasheet or MTK common design notice to get the recommendation bypass cap. value for VCC/VCO/VDDI power domains of eMMC.

Note 44-4: VDD2 VDDQ decoupling cap: closed to DRAM ball.
For other cap for PMIC [$>10\mu F$, at PMIC page]:
please also refer to MMD and layout guide for placement.



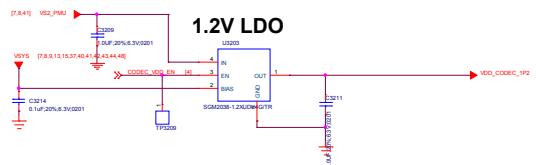
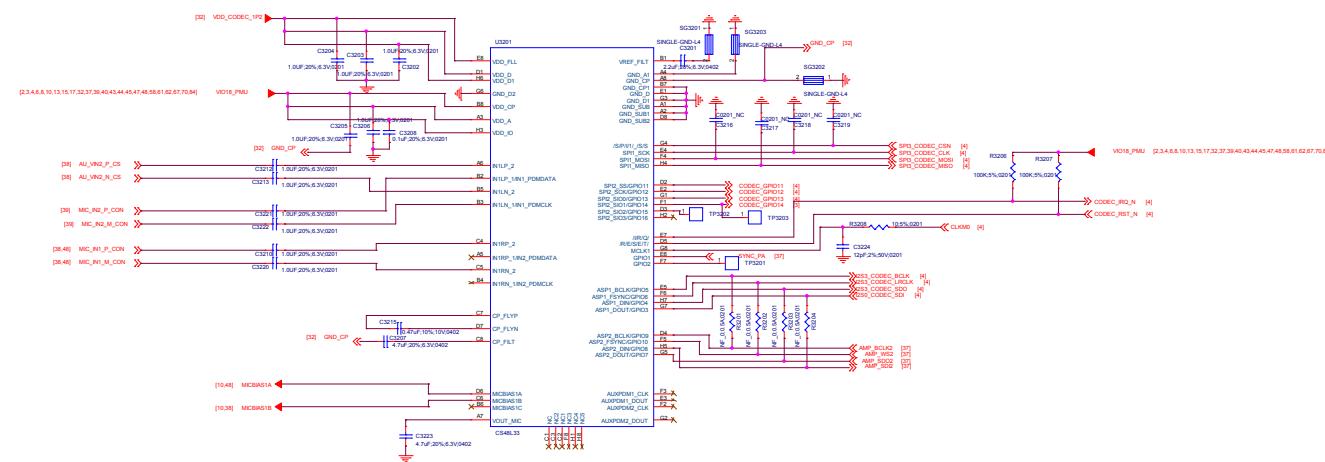
Schematic design notice of "44 Memory eMMC LPDDR4X"

Note 44-1: Please refer to power supply related page select VDRAM 2 / VDRAM output voltage properly for LPDDR4X

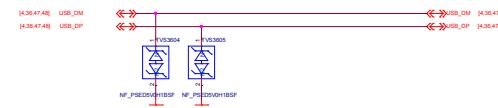
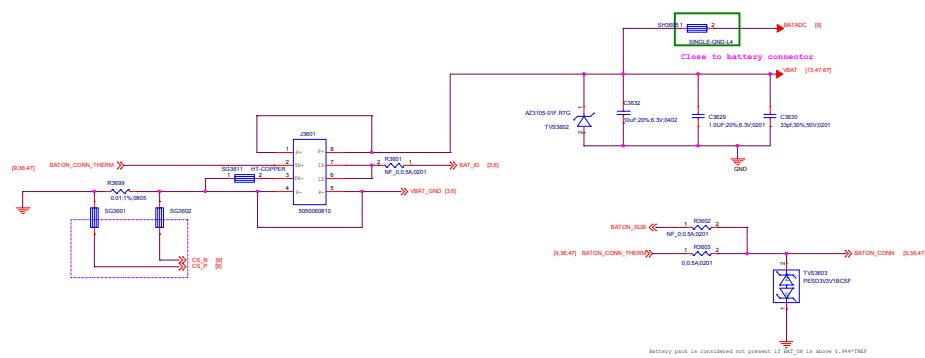
Note 44-2: DRAM ZQx resistor = 240ohm (1%) that must be connected to VDDQ

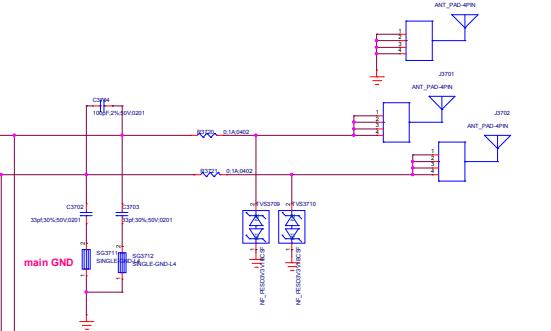
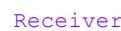
Note 44-3: Please refer to eMCP vendor's datasheet or MTK common design notice to get the recommendation bypass cap. value for VCC/VCCQ/VDDI power domains of eMM

Note 44-4: VDD2 VDDQ decoupling cap: closed to DRAM ball.
For other cap for PMIC [$>10\mu F$, at PMIC page]:
please also refer to MMD and layout guide for placement.

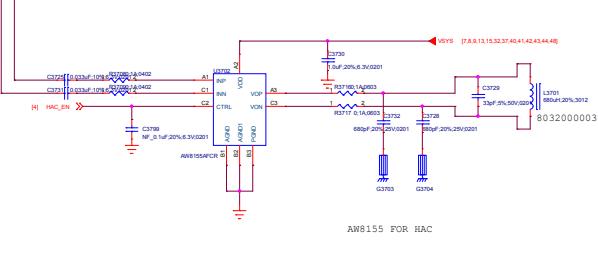


BATTERY CONNECTOR

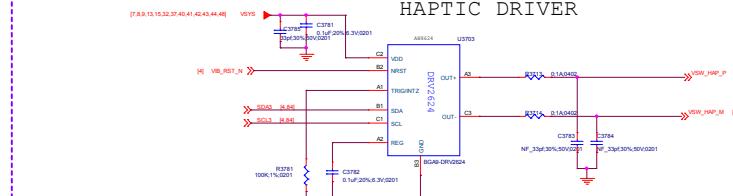




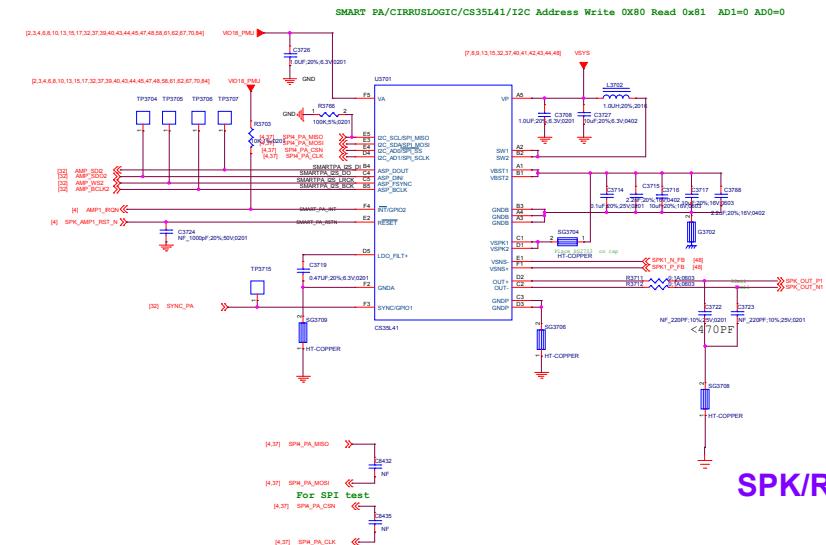
HAC



HAPTIC DRIVER



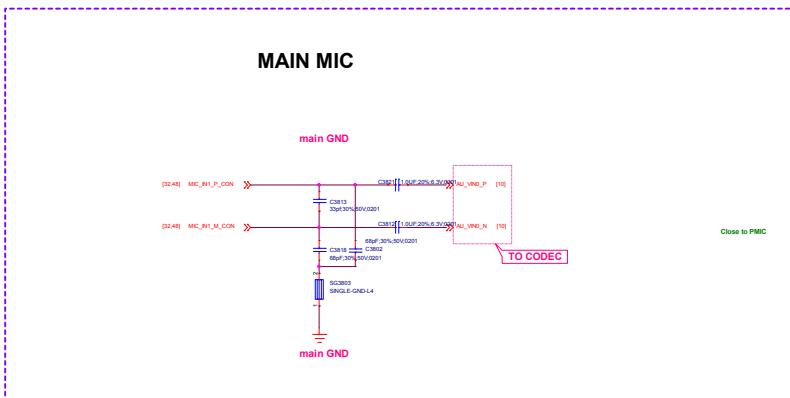
AUDIO PA



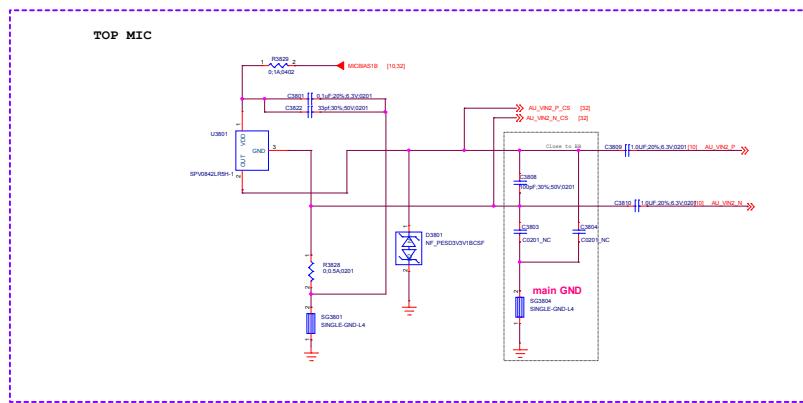
SPK/Receiver/Vibrator

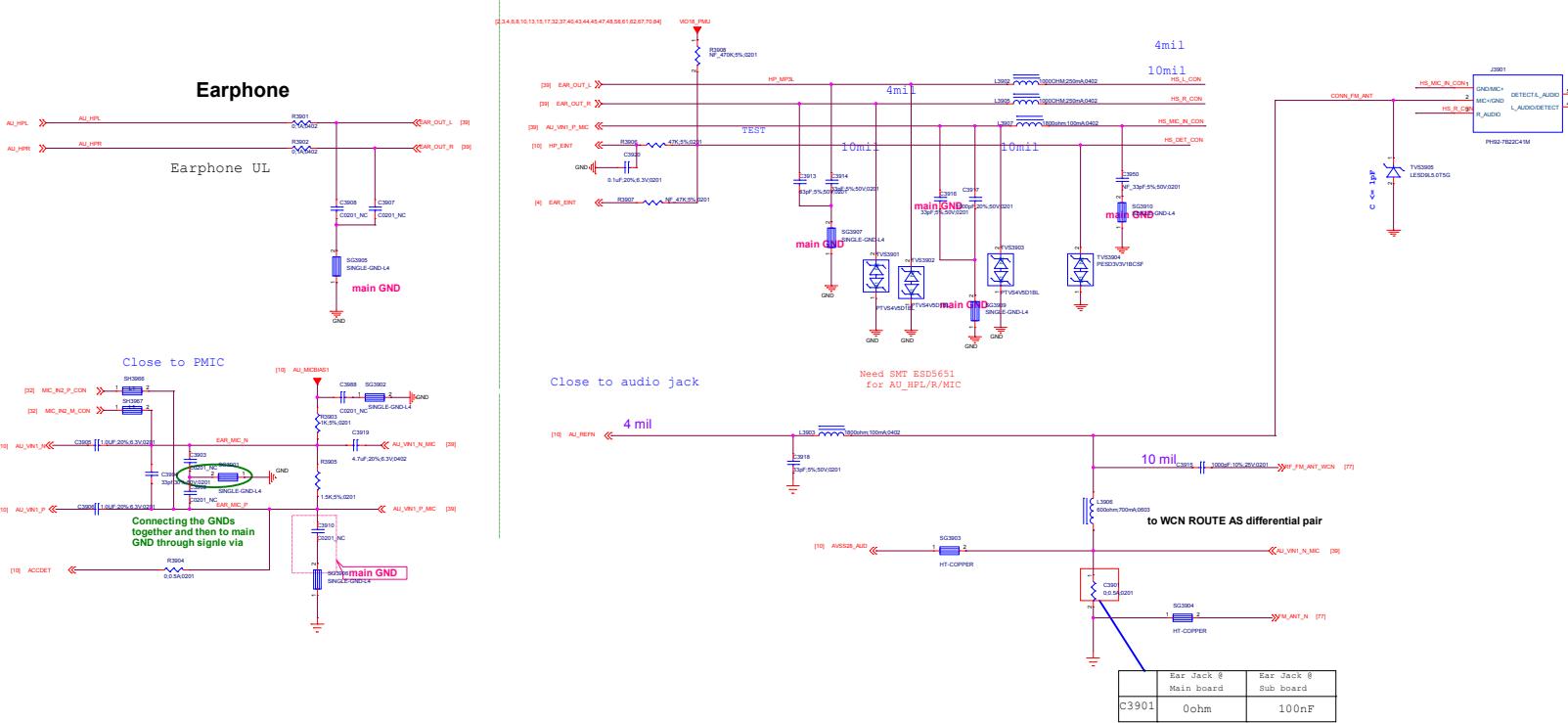
Title	37_SPK/Receiver/Vibrator	REV: V10
DOCUMENT NO.:	Design Name	Star D
DEPARTMENT:	WINGTECH-SH	DESIGNER: LILFENCLEI
WINGTECH		
Date:	Thursday, May 30, 2019	
		Sheet 23 of 68

MAIN MIC



TOP MIC





Schematic design notice of "62_PERI_AUDIO_IO" page.

Note 62-1: Part # of BEAD6202, BEAD6203, BEAD6204 and BEAD6205 needs changed to "BLM18BD102SN1" for high THD performance (-90dB) but this BOM change will results in FM RSSI 10dB degraded .

Note 62-2: Reserved Cap for CS/RS test, please double check multi-key function when used

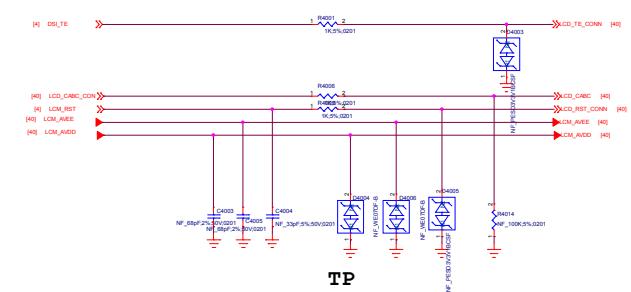
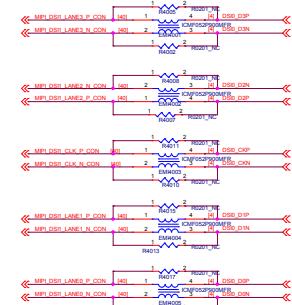
Note 62-3:		Earphone Jack 8 Main board	Earphone Jack 8 Sub board
K6513	0 ohm	100ns	

Note 62-4: Please Select ACC Mode for Operator Project to Pass Electrical MOS Test;
More Information refer to Audio/Speech Design Notice

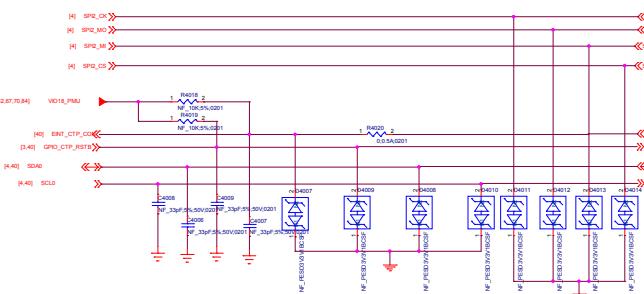
Note 62-5: Please select R6231 with 0402 size



Common Mode Filter

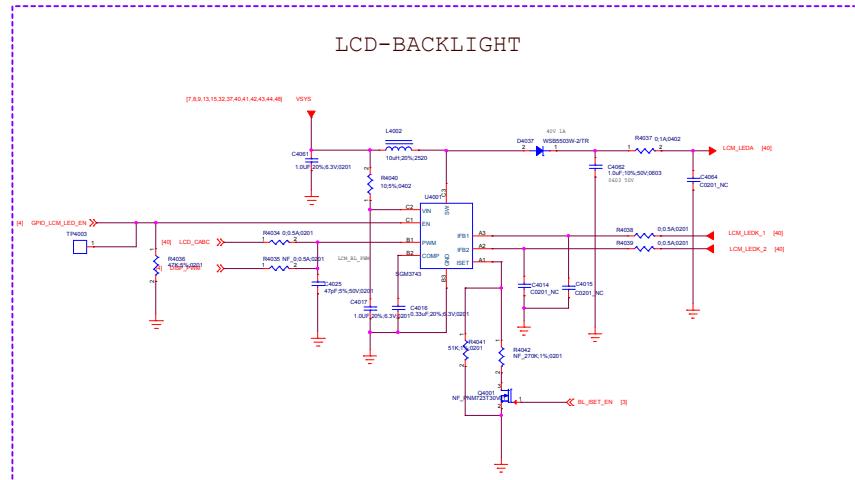
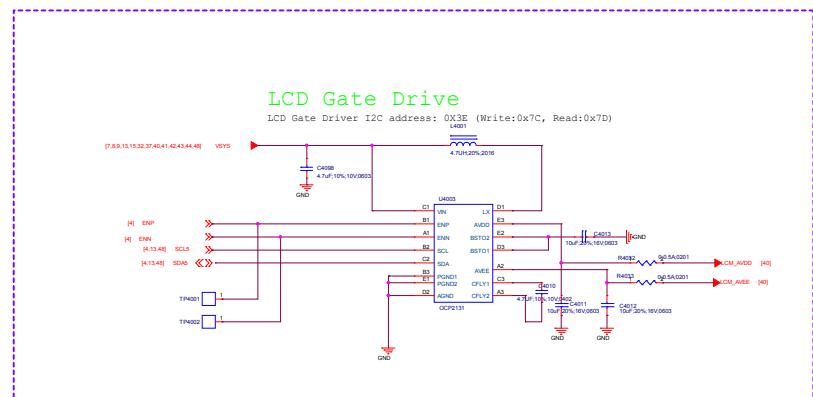


LCD-Connector



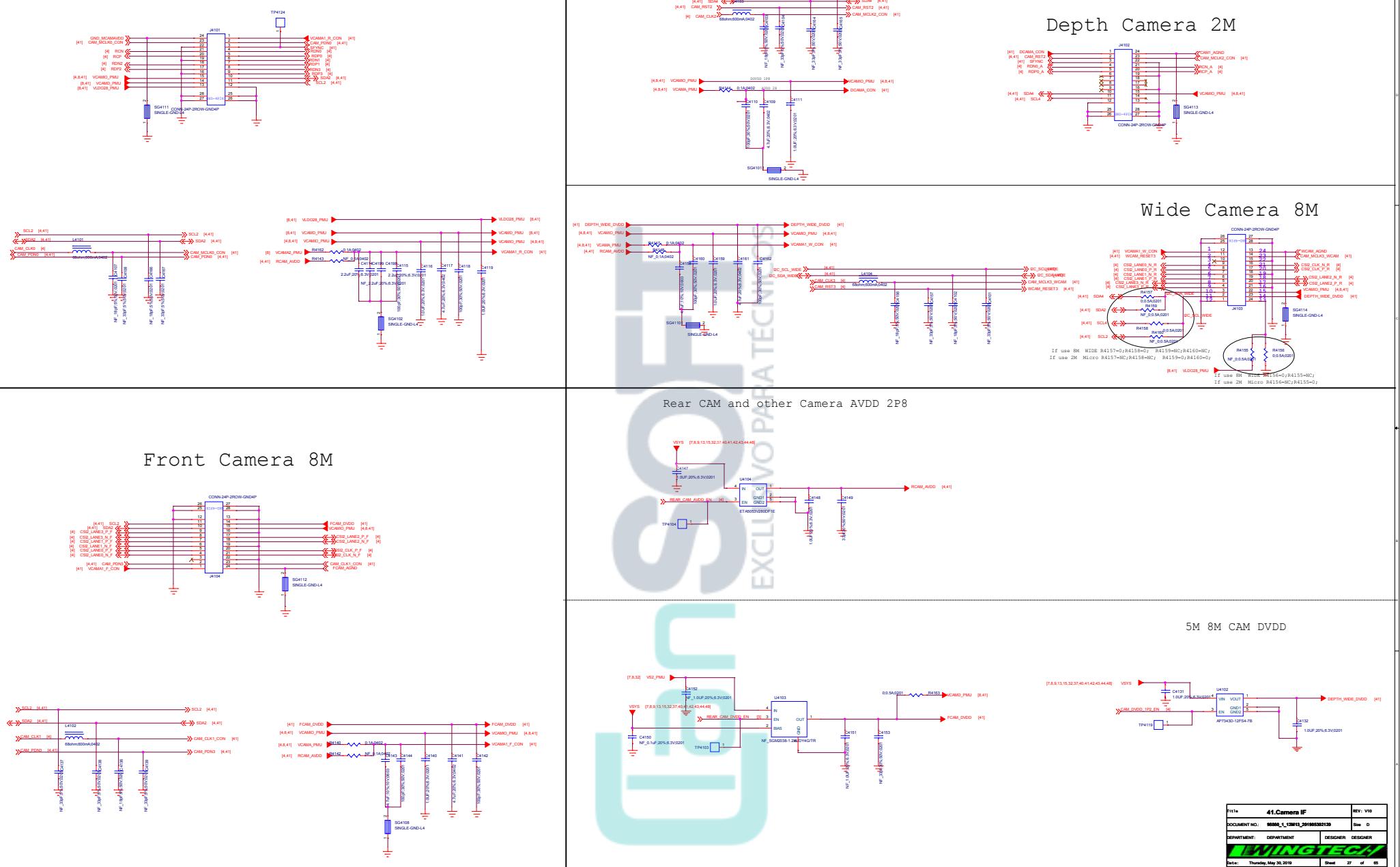
LCD Gate Drive

LCD Gate Driver I2C address: 0X3E (Write:0x7C, Read:0x7D)

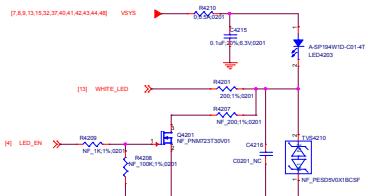


Title	40_LCD/CTP IF	REV.
DOCUMENT NO.:	Design Name	Sheet
DEPARTMENT:	WINGTECH	DESIGNER: LUFENGHE
WINGTECH	Date: Thursday, May 30, 2019	Sheet 26 of 65

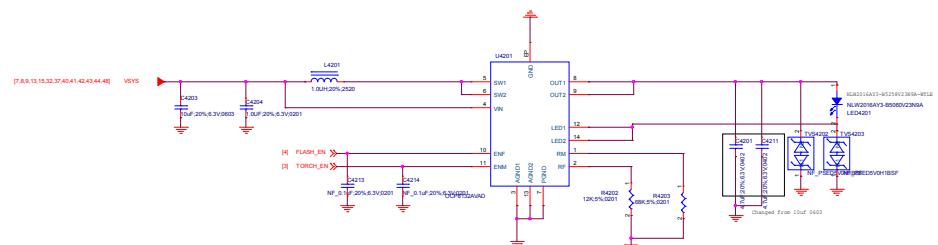
Main Camera 13M



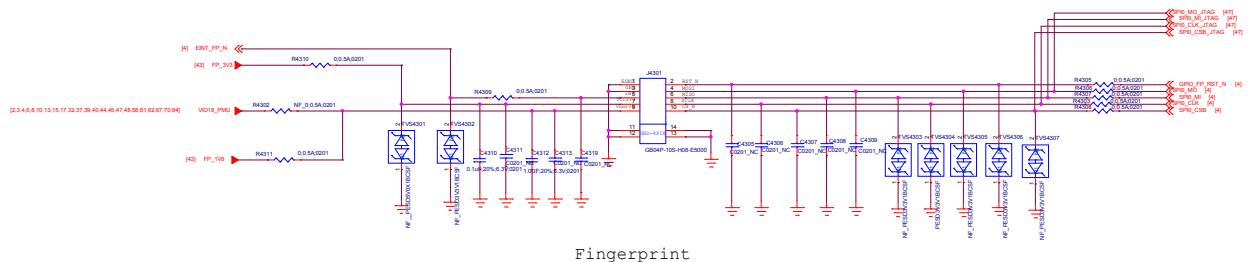
Title	41.Camera IF	REV: V10
DOCUMENT NO.:	90880_1_12M13_201905302120	Size D
DEPARTMENT:	DEPARTMENT	DESIGNER: DESIGNER
WINGTECH		



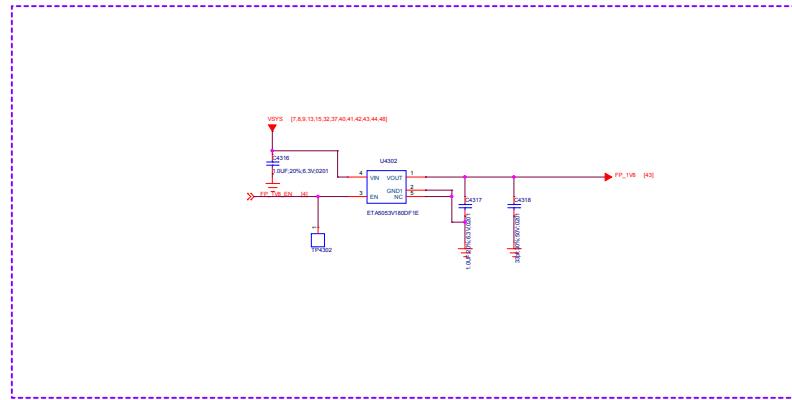
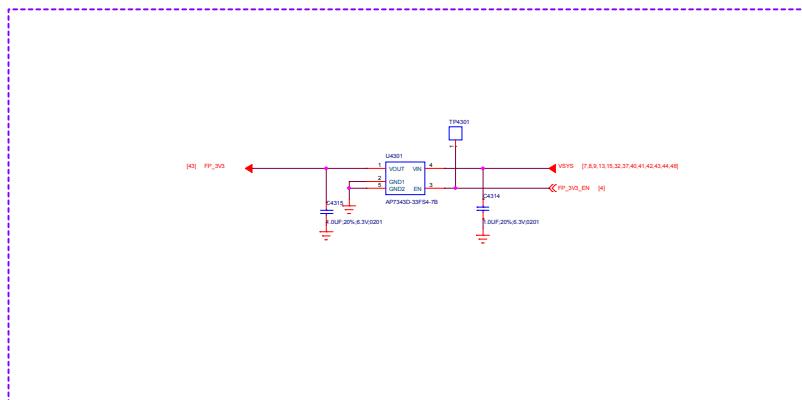
Input and output cap voltage confirm ?



Fingerprint



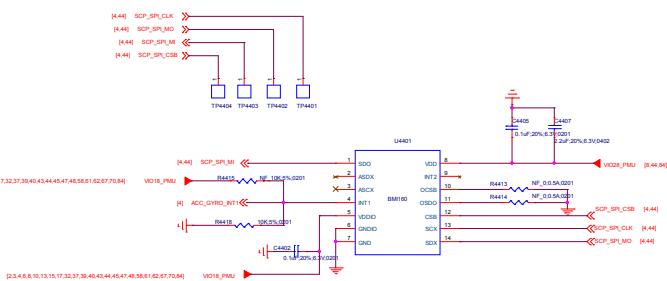
Fingerprint



Title	43.Fingerprint	REV:	V10
DOCUMENT NO.	8888_1_128x128_201905221229	Sheet	D
DEPARTMENT	Wiegand-S2	DESIGNER	DESIGNER
LIVINGTECH			

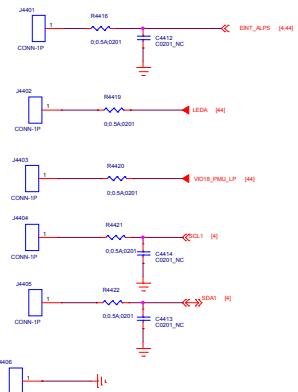
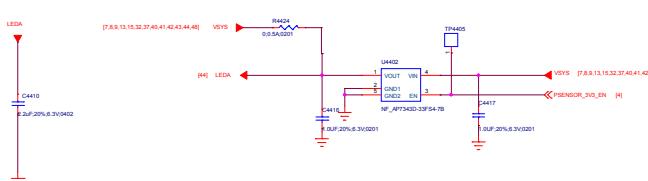
Date: Thursday, May 20, 2010 Sheet 29 of 60

ACCELEROMETER+GYRO

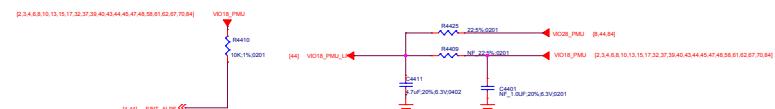


ALP-Sensor

Proximity Sensor



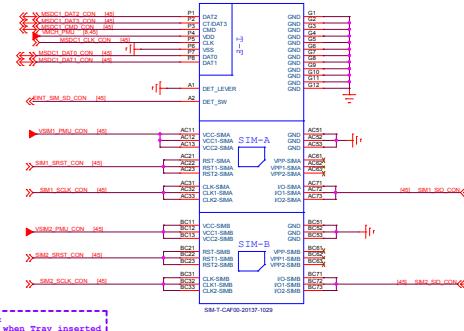
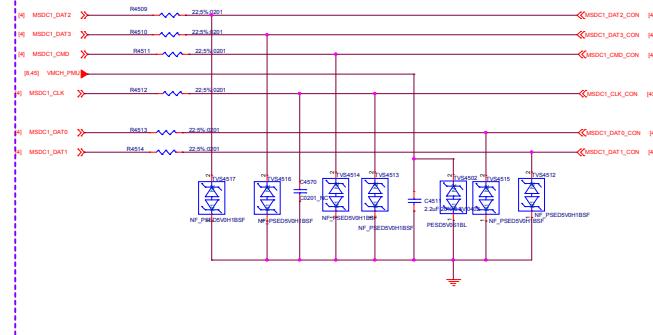
Ambient Light Sensor



44_Sensor		REV: V10
DOCUMENT NO.:	Design Name	Sheet D
WINGTECH-GH		
LUFENGLEI		

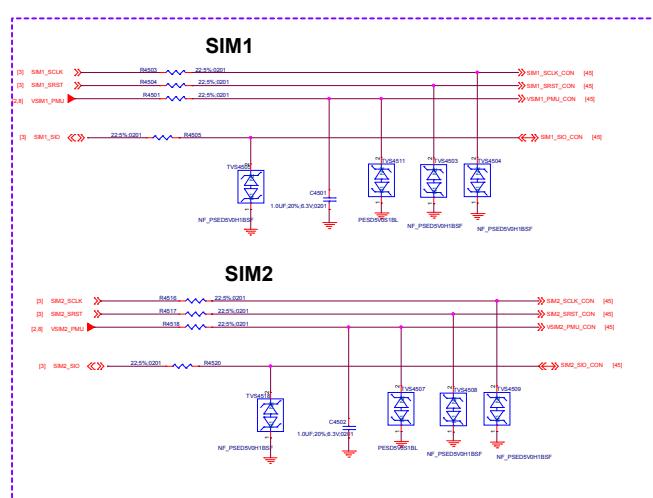
Date: Thursday, May 30, 2019

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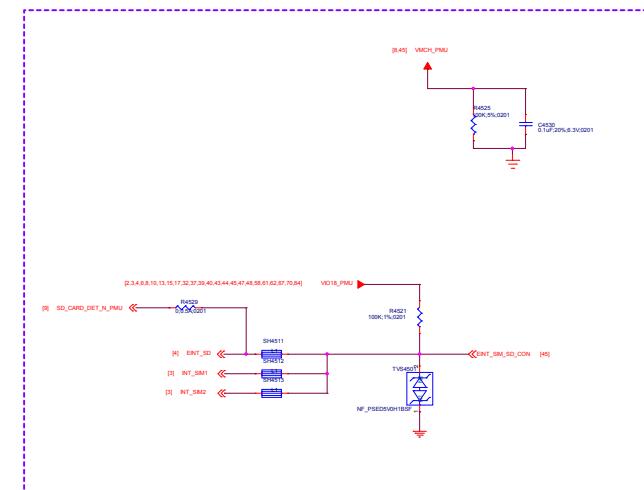


SIM&SD Connector

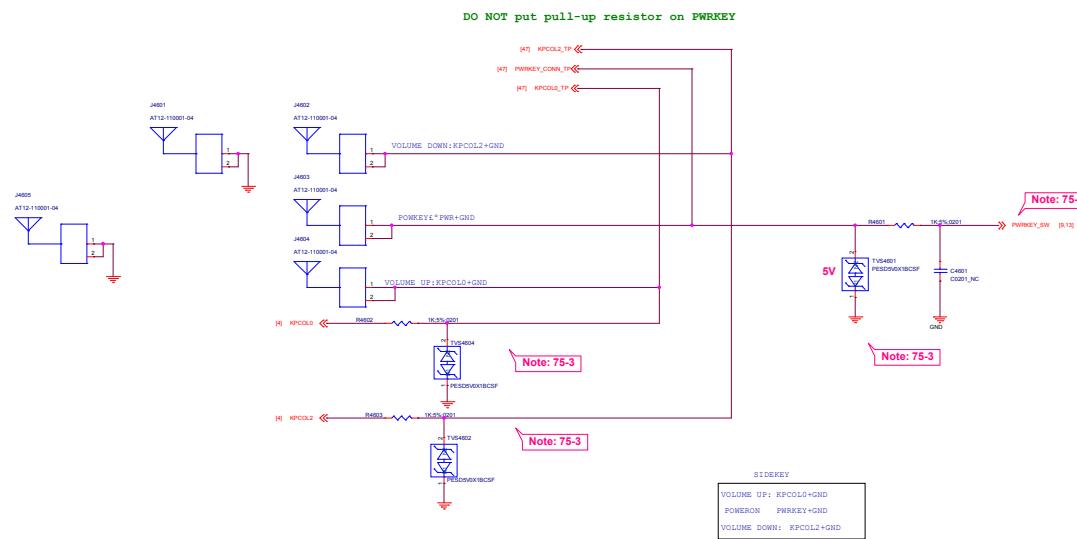
SIM1



SIM2



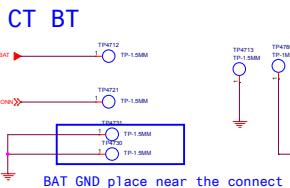
Power Key / Key Pad



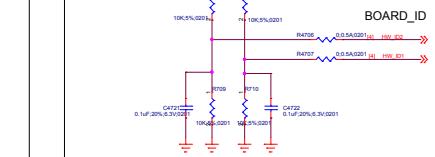
Note 75-1: DO NOT put pull-up resistor on PWRKEY
 Note 75-2: Volume Up: KPCOL0+GND
 Volume Down: KPCOL2+GND

SIDEKEY
 VOLUME UP: KPCOL0+GND
 POWERON PWRKEY+GND
 VOLUME DOWN: KPCOL2+GND

Title	46_Sidekey	Rev.	V10
DOCUMENT NO.:	Design Name	See	D
DEPARTMENT:	WINGTECH-SH	DESIGNER:	LUFENG.LI
Date:	Thursday, May 30, 2013	Sheet:	32 of 81



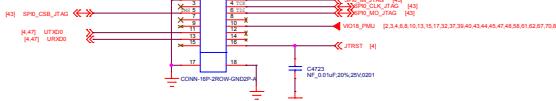
DEVICE MODE CONF



KEYS



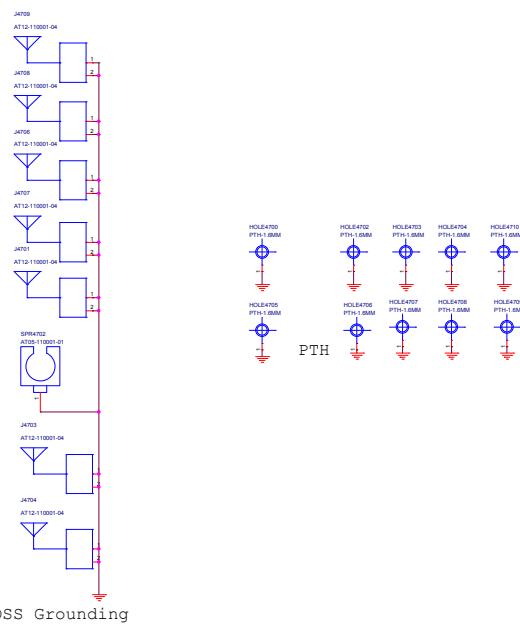
JTAG CONNECTOR



UART

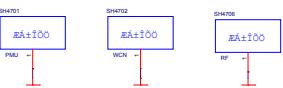


Grounding



SHIELDING

BOT



TOP



MARK



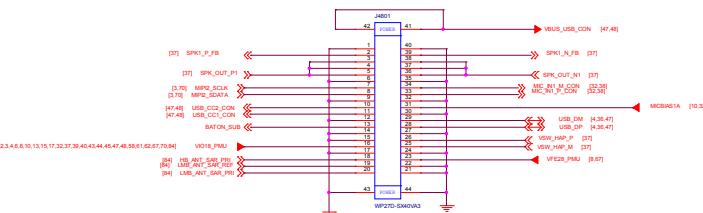
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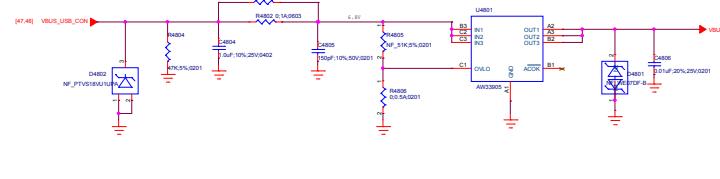
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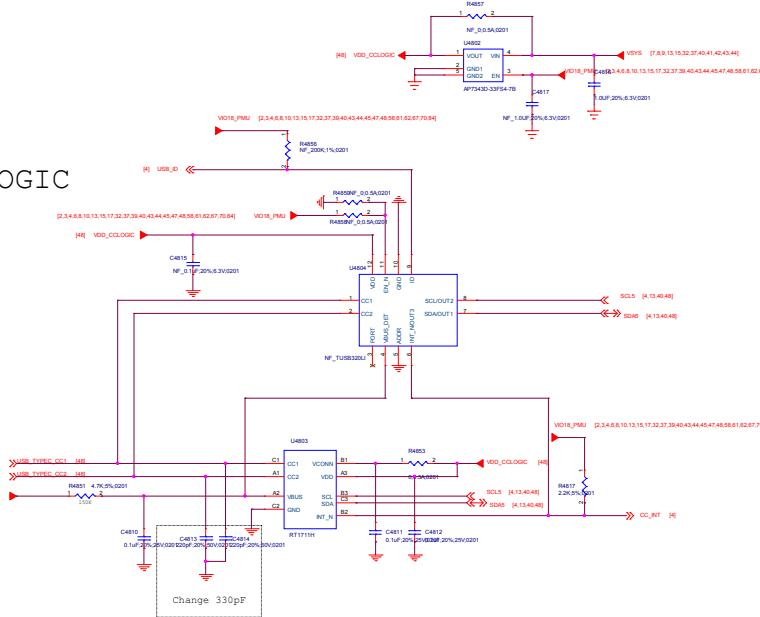
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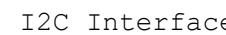
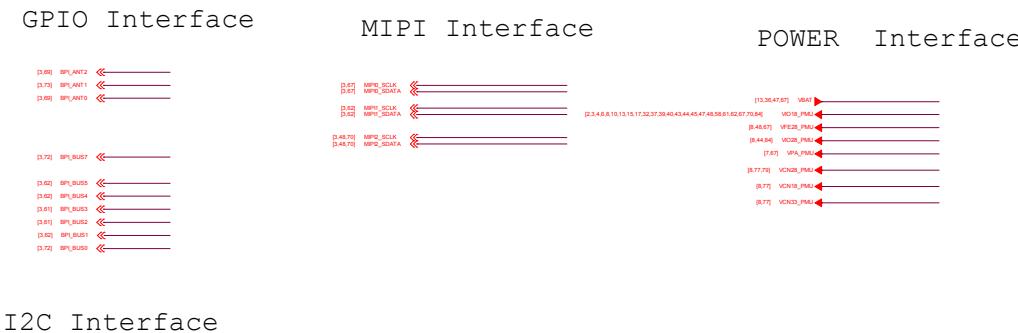


OVP



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File	Print Preview	Print Preview

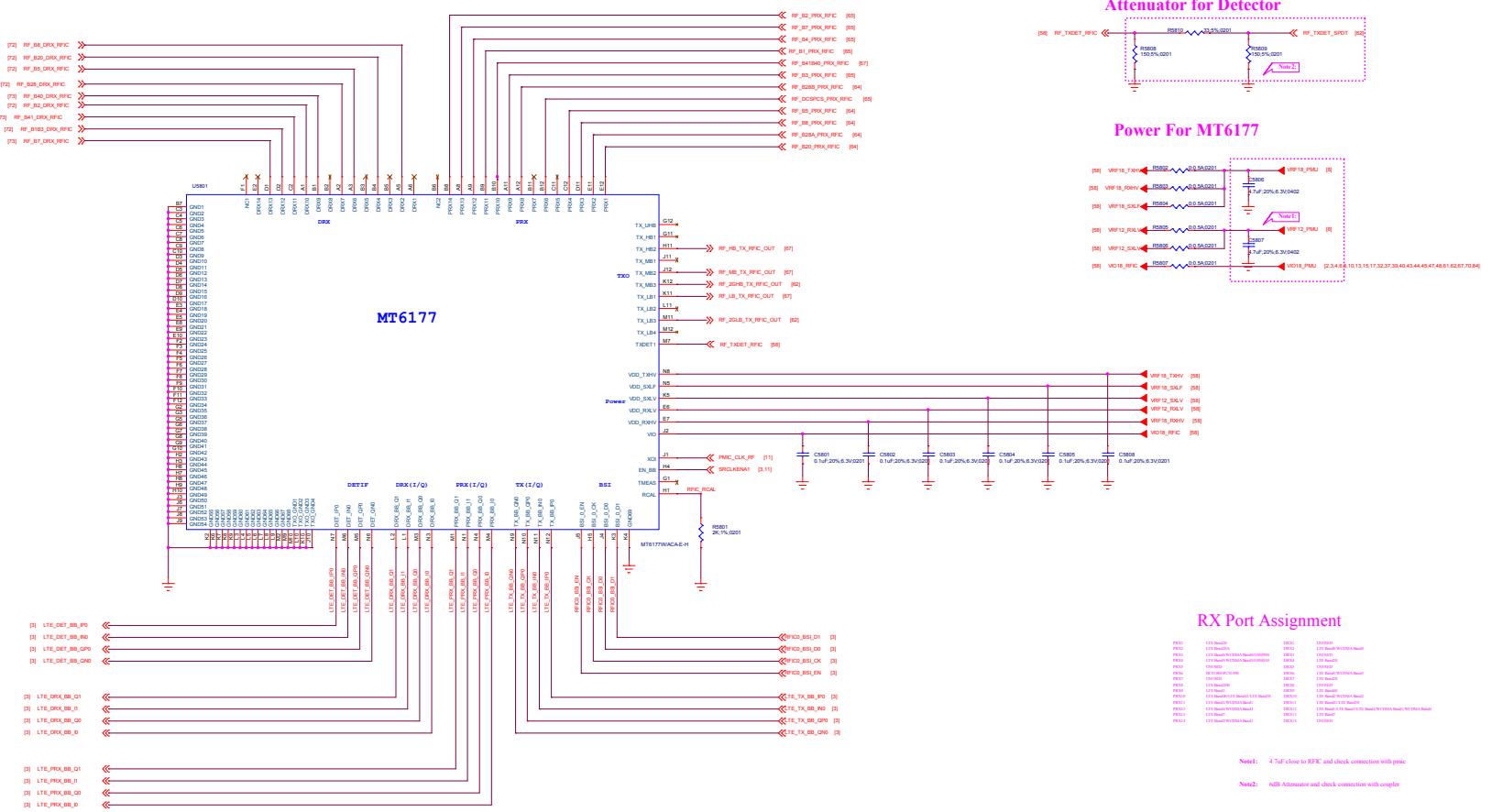
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Part No:	Reserved	REV: V10
DOCUMENT NO.:	Design Name	Sheet A1
DEPARTMENT:	WINGTECH	DESIGNER: LEIPENGZI
DATE:	Thursday May 23, 2019	Sheet 1 of 10
WINGTECH		

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Part No:	Reserved	REV: V10
DOCUMENT NO.:	Design Name	Sheet A1
DEPARTMENT:	WINGTECH	DESIGNER: LEIPENGZI
DATE:	Thursday May 23, 2019	Sheet 00 of 00
WINGTECH		

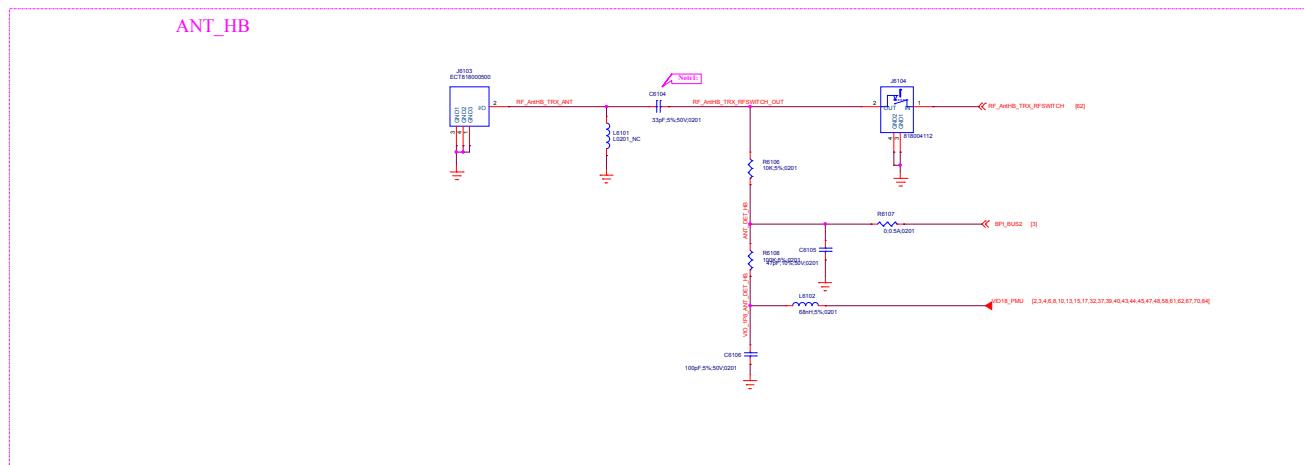
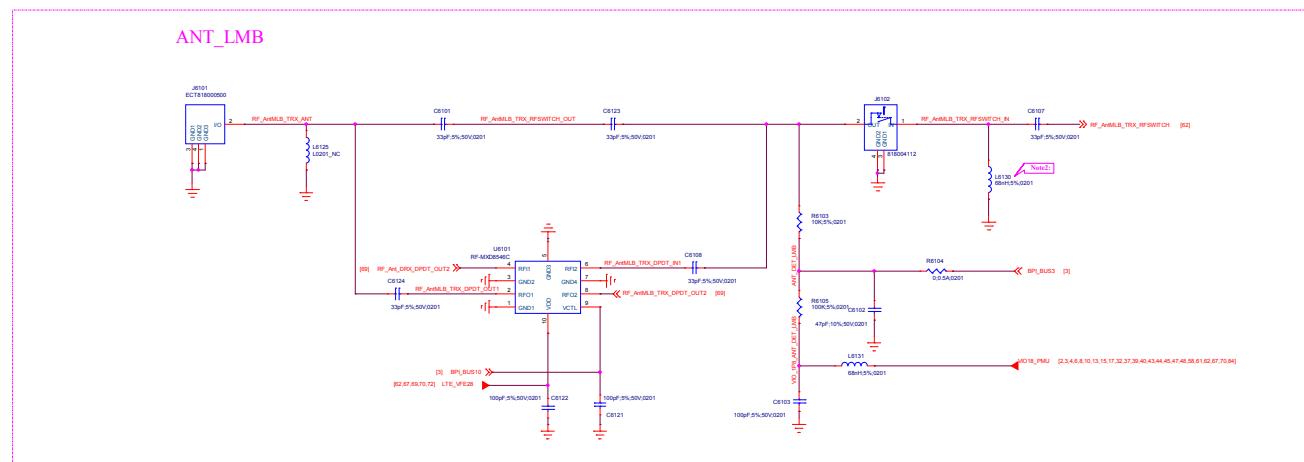
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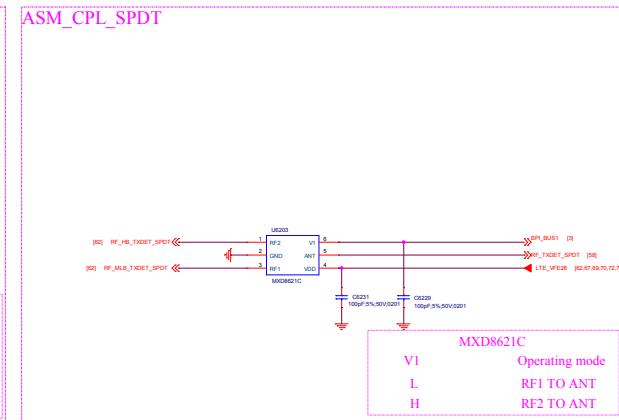
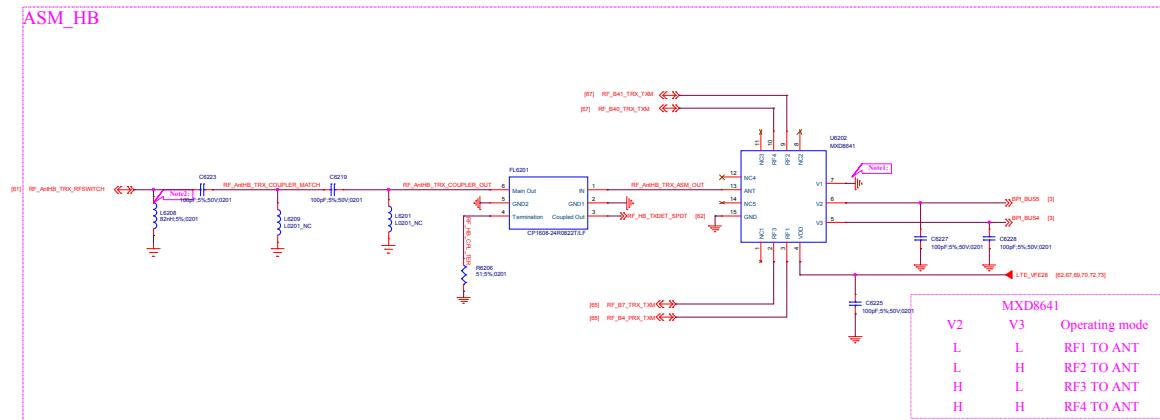
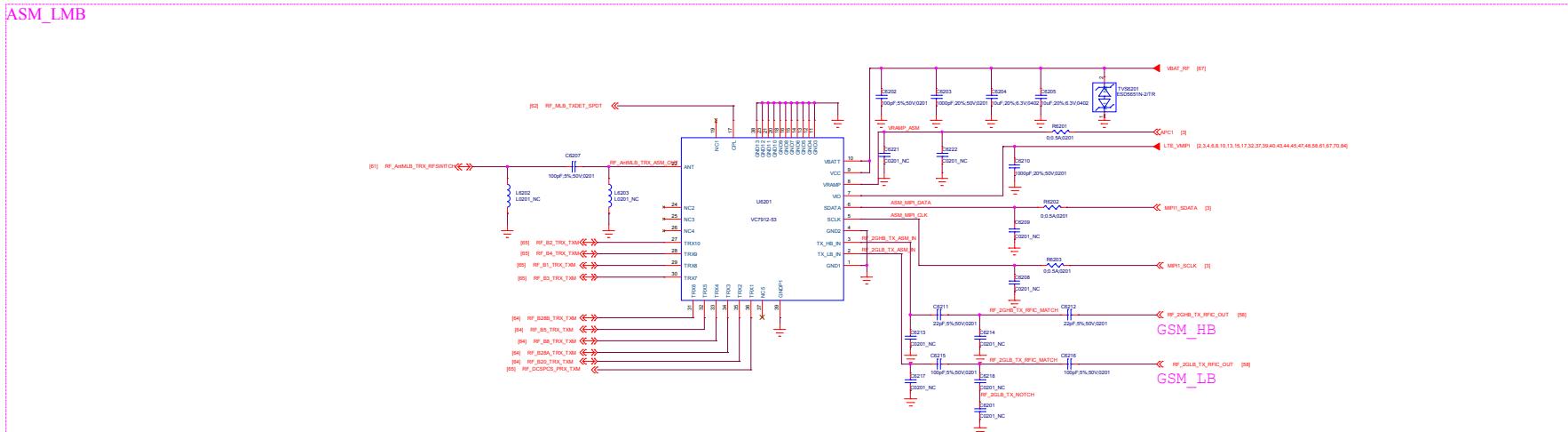
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Note1: RF SWITCH DETECT,MUST BE CAP IF DPDT IS WITHOUT DC BLOC

Note2: MUST BE IND FOR RF SWITCH DETE

Title: REV: V10
DOCUMENT NO Design Name = 98986_1_12M13_201905302125pm D
DEPARTMENT: DEPARTMENT = WINGTECH DESIGNER: DESIGNER = LL
WINGTECH
Date: Page Modify Date = Thursday, May 30, 2019 40 of 65



Note: MND8641 YI CAN GROUP CONFIRMED WITH FAE

Note2: MUST BE IND FOR RF SWITCH DETECT

Title	Page Name = 62_Primary_ASM	REV: V10
DOCUMENT NO.:	Design Name = 98869_1_128413_201905300800 D	
DEPARTMENT:	DEPARTMENT = WINGTECH	DESIGNER = LUFEI
WINGTECH		
Date:	Drawn/Metric Date: / Threaded: Mon 27 May 2019	Digitized Date: / /

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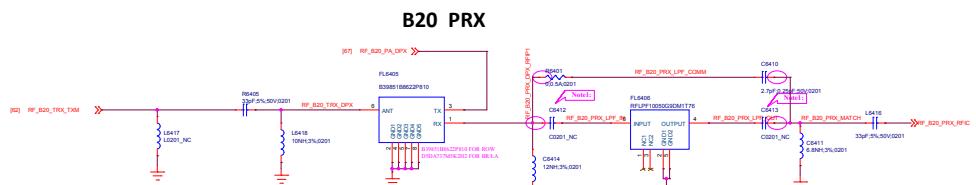
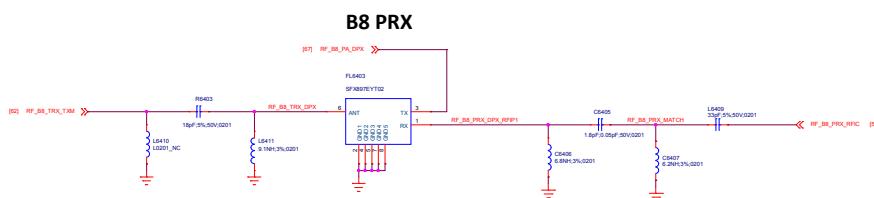
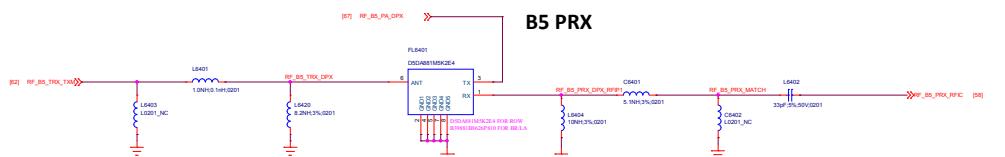
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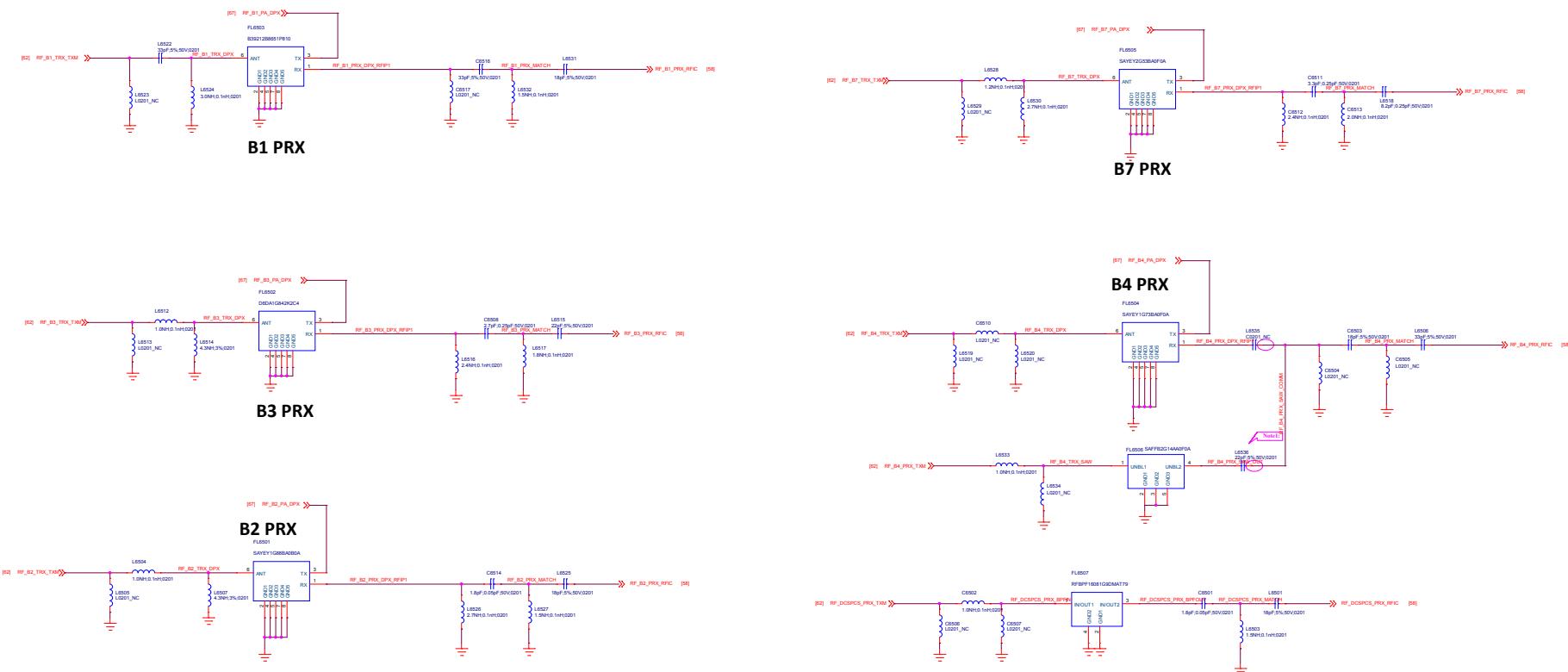
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Page	Document Number	
All	<Doc>	Rev 1.0
Date	Thursday, May 20, 2009	
	Sheet	42
	of	65



Note: COMPARABLE DESIGN FOR LSC AND SHARE RAD IN BCE

Title	Page Name = 64_TRX_LB	REV: V10
DOCUMENT NO:	Design Name = 98000_1_12M13_201903200400	D
DEPARTMENT:	DEPARTMENT = WINGTECH	DESIGNER = LUFENG
WINGTECH		
Date:	Drawn/Mfd Date:	Thursday, Mar 20, 2019
		13 of 15



Band Note:

Note1: COMPATIBLE DESIGN FOR B4 PRX SAW AND DUPLEXER,AND SHARE PAD IN P

Title	Page Name = 65_TRX_MHB	REV: V10
DOCUMENT NO.:	Design Name = 9896_1_12M13_2619053	9896 D
DEPARTMENT:	DEPARTMENT = WINGTECH	DESIGNER = LIUJINQ
WINGTECH		
Date:	Page Modify Date = Thursday, Mar 20, 2014 10:44 AM	44 of 44

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File	Document Number	13
File	Print	Print

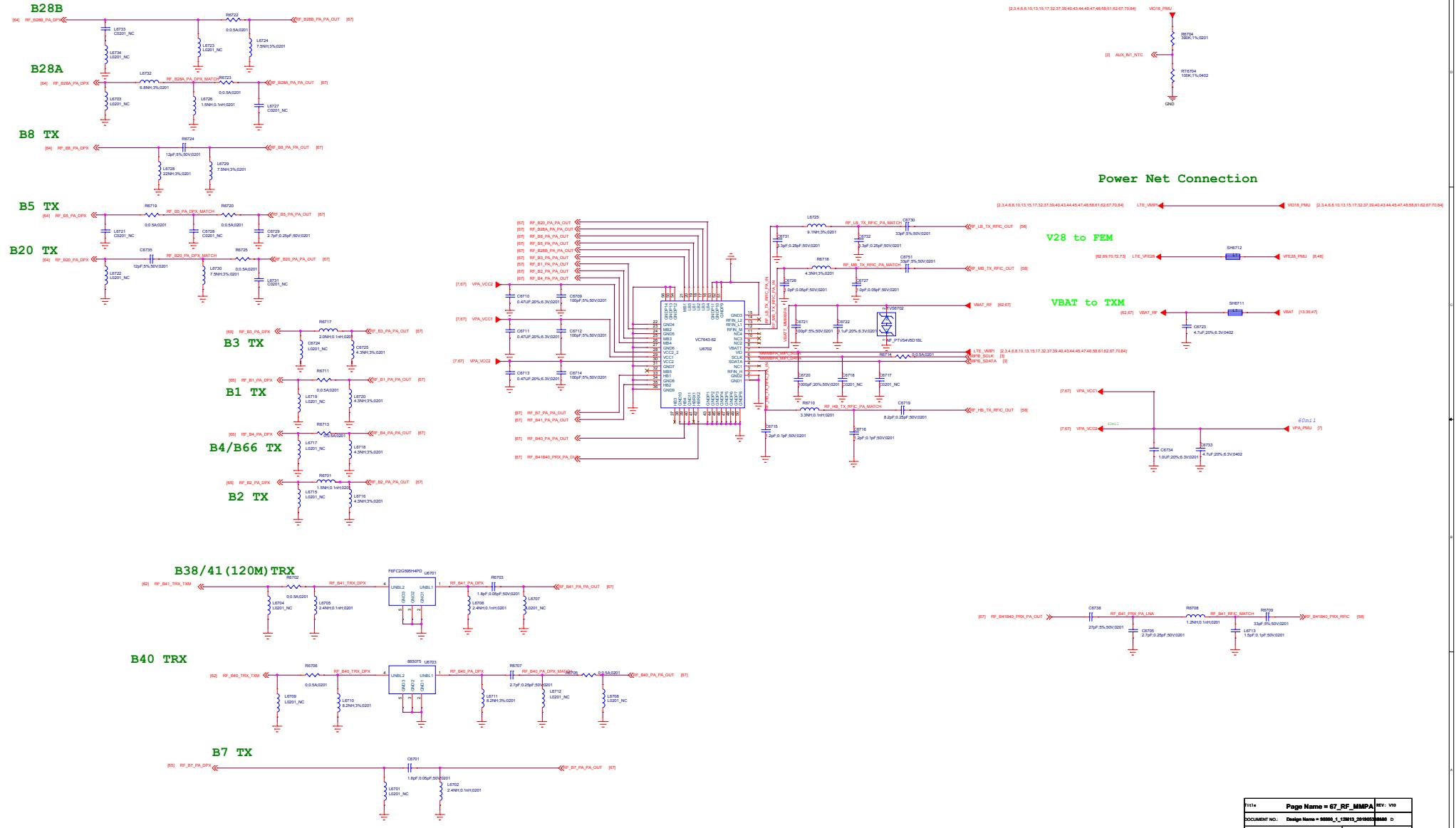
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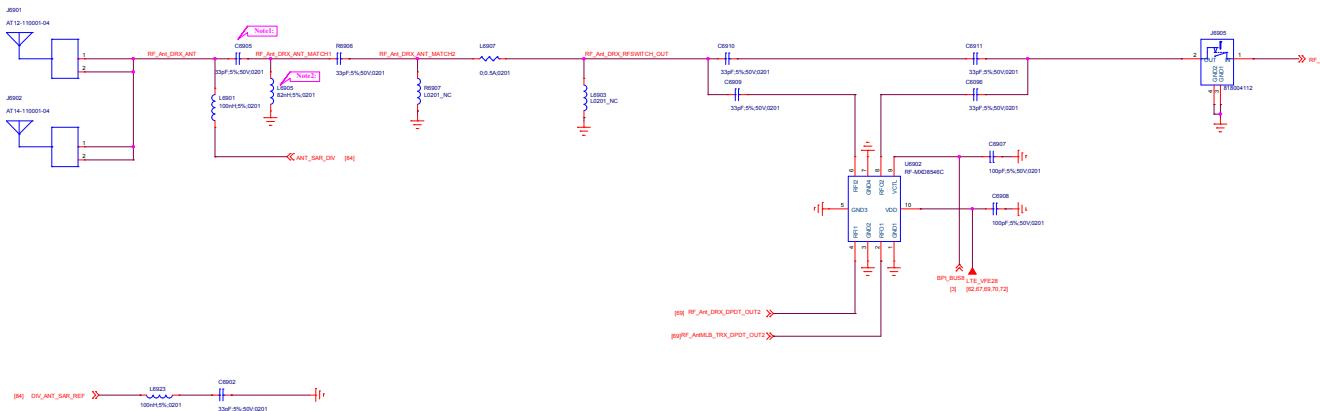
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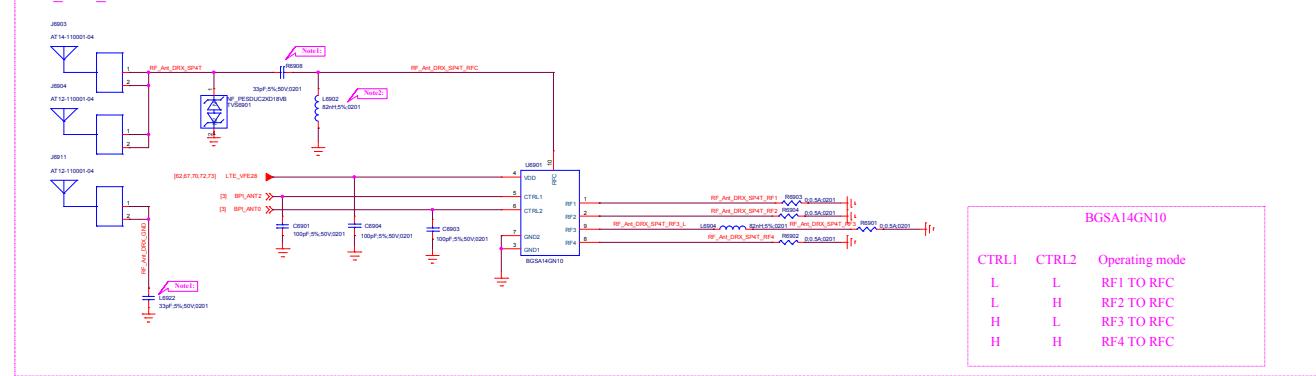
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All	<Doc>	Page 1 of 10
Last Modified: May 20, 2013		Printed:
		47
		58

ANT_DIV_FEED



ANT_DIV_TUNER



Note1: MUST BE CAP FOR SAR DETECT DESIGN

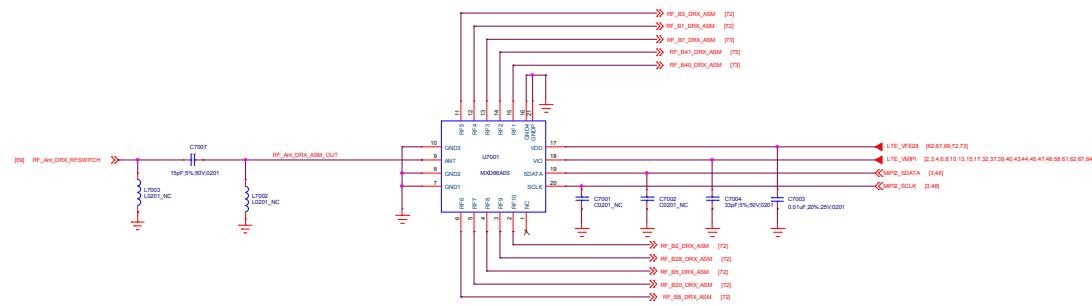
Note2: MUST BE IND FOR SAR DETECT DESIGN

Note3: OR RES IS RESERVED FOR SAR SENSOR DESNSE. PLACE CLOSE TO ANTENNA

Note4: share pad in PCB

Page Name = 69_Diversity	Rev	Ver
DOCUMENT NO.: Design Name = 58860_1_C9M13_20180508	0	0
DEPARTMENT: DEPARTMENT = WINGTECH DESIGNER = LIAPOLIS		
WINGTECH		

Date: Page Modify Date = Thursday, May 30, 2019 Sheet 46 of 62



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Part No:	Reserved	REV: V10
DOCUMENT NO.:	Design Name	Sheet A1
DEPARTMENT:	WINGTECH	DESIGNER: LUFENGZI
DATE:	Thursday May 23, 2019	Sheet 00 of 00
WINGTECH		

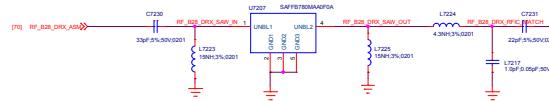
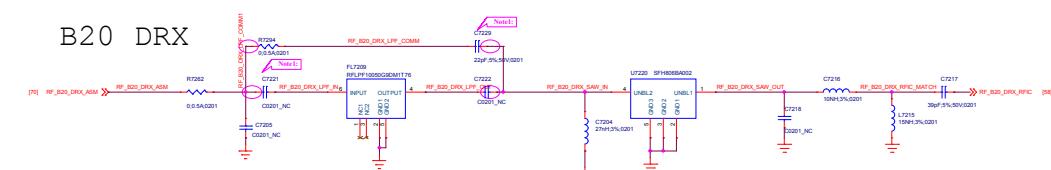
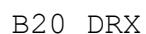
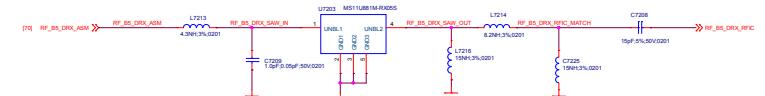
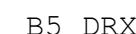
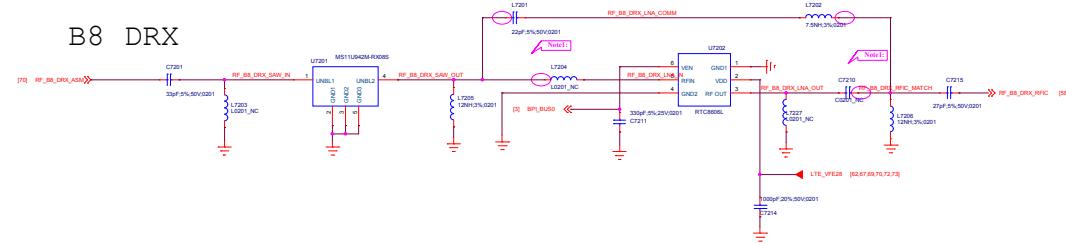
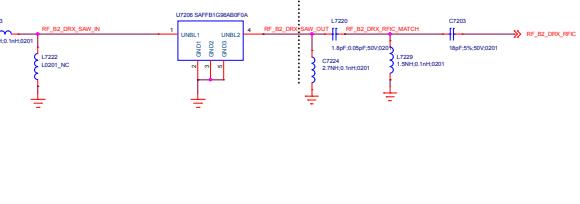
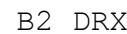
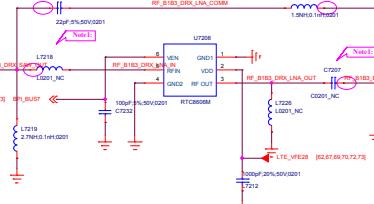
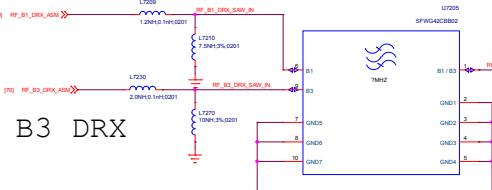
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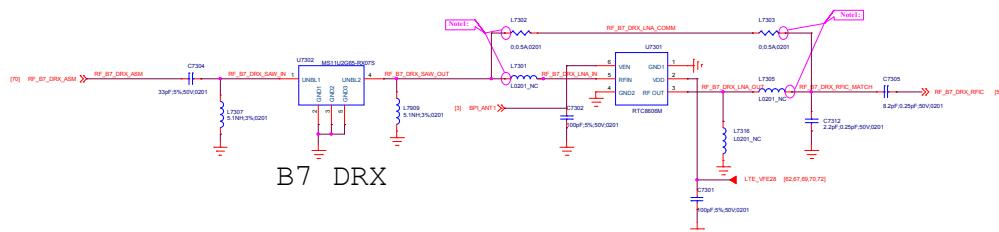
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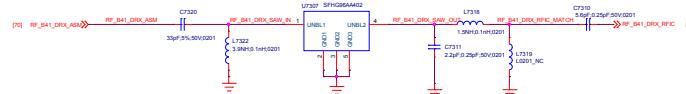


Note: COMPATIBLE DESIGN AND SHARE PAD IN PC.

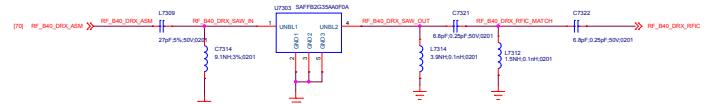
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DOCUMENT NO.:	Design Name = 98860_1_12M123_201903020900	D
DEPARTMENT:	DEPARTMENT = WINGTECH	DESIGNER = LUF
WINGTECH		



B7 DRX



B38/41 DRX



B40 DRX

Note 1: COMPATIBLE DESIGN, AND SHARE PAD IN PCB

Page Name = 73_DRX_NB	Rev. V10
DOCUMENT NO.: Design Name = 58860_1_CMB13_20180502	D
DEPARTMENT: DEPARTMENT = WINGTECH-SI	DESIGNER: DESIGNER = LUMIENG
WINGTECH	Date : Page Modify Date = Thursday, May 24, 2018 Sheet 52 of 65

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Part No:	Reserved	REV: V10
DOCUMENT NO.:	Design Name	Sheet A1
DEPARTMENT:	WINGTECH	DESIGNER: LEIPENGZI
DATE:	Thursday May 23, 2019	Sheet 14 of 60
WINGTECH		

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Part No:	Reserved	REV: V10
DOCUMENT NO.:	Design Name	Sheet A1
DEPARTMENT:	WINGTECH	DESIGNER: LEIPENGZI
DATE:	Thursday May 23, 2019	Sheet 00 of 00
WINGTECH		

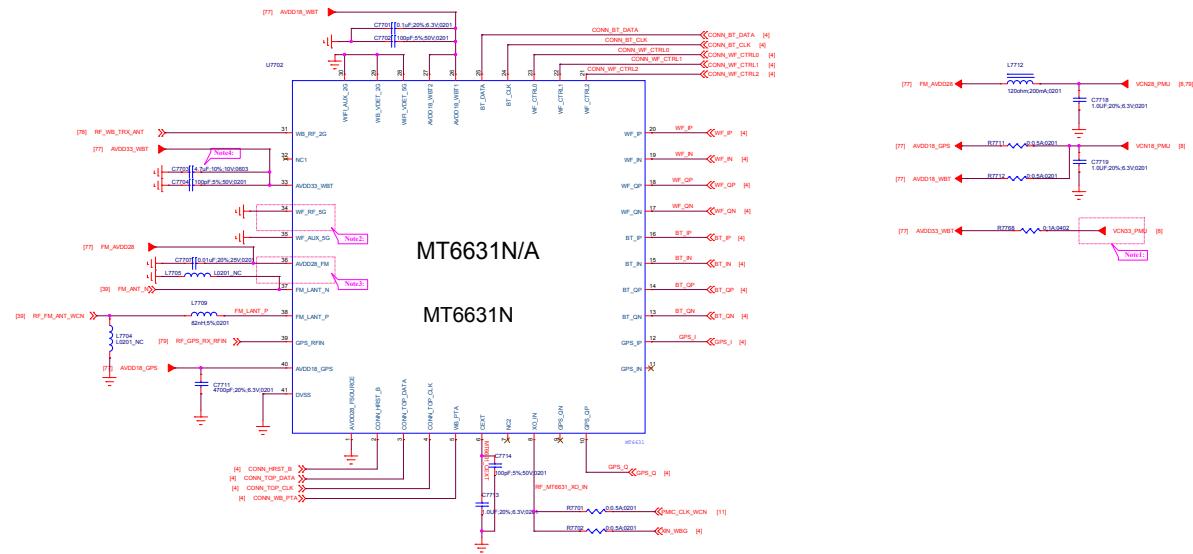
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Note1: If WiFi 5G were no need, VCN33 could be chosen from PMIC output (VCN33_PMU)

Note 2: If WiFi 5G not succeed, connect min 340WF RF 5G to GN1

Note 2: Pin 26 (AMDD2K_EMO) must be connected to VCN2K_EMO if EMU not connect.

Title	Page Name = 77_WCN_MT6851	V10
DOCUMENT NO.:	Design Name = 98860_1_128M13_201905030950	D
DEPARTMENT:	DEPARTMENT = WINGTECH	DESIGNER: DESIGNER = LUFENG
<i>WINGTECH</i>		

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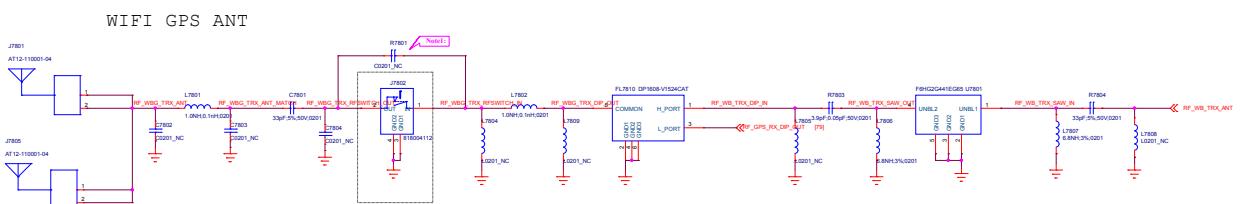
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Note1: COMPATIBLE DESIGN FOR WIG RF SWITCH USE OR AFTER MP

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File:	Reserved	Rev. V10
DOCUMENT NO.:	Design Name	Rev. D
DEPARTMENT:	WINGTECH-SH	DESIGNER: LAFENCE
Date: Thursday, May 20, 2010	Sheet	57 of 65

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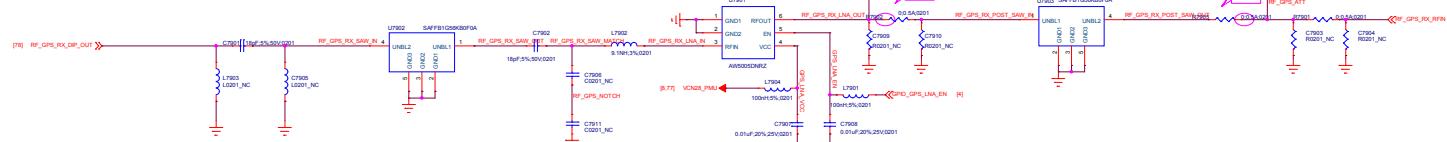
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Name: COMPATIBLE DESIGN FOR GPS PORT SAWSHARE PAD IN PCB

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Name	Reserved	Rev. V1D
DOCUMENT NO.:	Design Name	Sheet D
DEPARTMENT:	WINGTECH-SH	DESIGNER: LAFENGLE
Date: Thursday, May 20, 2010	Sheet 58	of 65

WINGTECH

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Part No:	Reserved	REV: V10
DOCUMENT NO.:	Design Name	Sheet A1
DEPARTMENT:	WINGTECH	DESIGNER: LUFENGZI
DATE:	Thursday May 23, 2019	Sheet 00 of 00
WINGTECH		

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Part No:	Reserved	REV: V10
DOCUMENT NO.:	Design Name	Sheet A1
DEPARTMENT:	WINGTECH	DESIGNER: LEIPENGZI
DATE:	Thursday May 23, 2019	Sheet 00 of 00
WINGTECH		

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File:	10_BB_POWER_PDN	Rev.: V10
DOCUMENT NO.:	Design Name	Size D
DEPARTMENT:	WINGTECH-SZ	DESIGNER: LUOPENGL
Date:	Thursday, May 20, 2010	Sheet 1 of 65

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Part No:	Reserved	REV: V10
DOCUMENT NO.:	Design Name	Sheet A1
DEPARTMENT:	WINGTECH	DESIGNER: LUFENGZI
DATE:	Thursday May 23, 2019	Sheet 02 of 02
WINGTECH		

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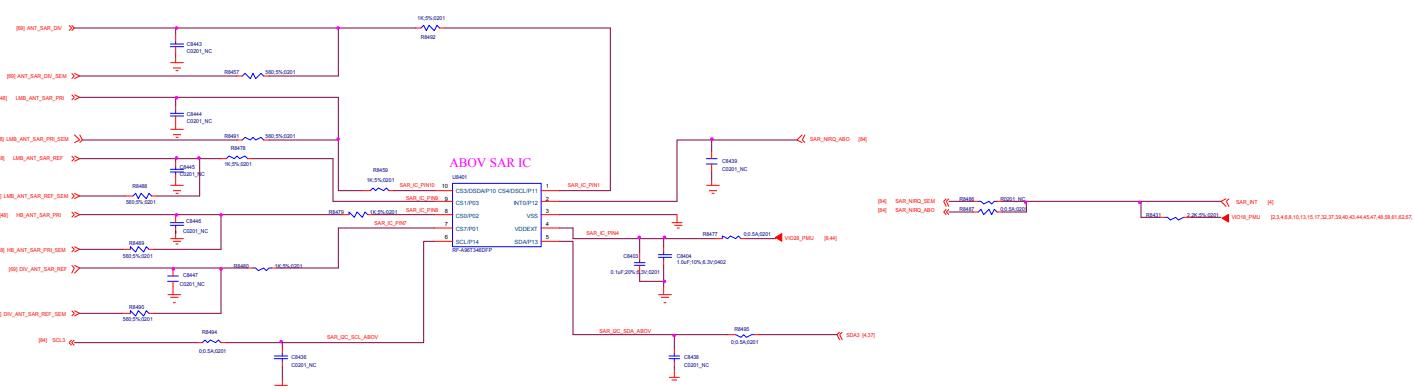
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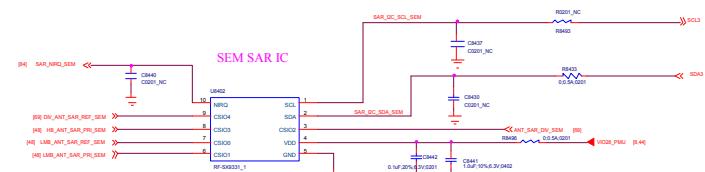
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Printed	Reserved	Rev. V10
DOCUMENT NO.	Design Name	Sheet A1
DEPARTMENT:	WINGTECH-SH	DESIGNER: LEIPEIGE
DATE:	Thursday, May 21, 2015	Drawn:

WINGTECH

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Title:	Reserved	REV: V10
DOCUMENT NO.:	Design Name	Size: A1
DEPARTMENT:	WINGTECH	DESIGNER: LEUNGCHI
Date: Thursday, May 30, 2019		Sheet 64 of 65
WINGTECH		

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Part No:	Reserved	REV: V10
DOCUMENT NO.:	Design Name	Sheet A1
DEPARTMENT:	WINGTECH	DESIGNER: LEIPENGZI
DATE:	Thursday May 23, 2019	Sheet 00 of 00
WINGTECH		

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